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AN EFFICIENT NUMERICAL TECHNIQUE  
FOR  
CALCULATING THERMAL SPREADING RESISTANCE

Final Report

8 February 1973

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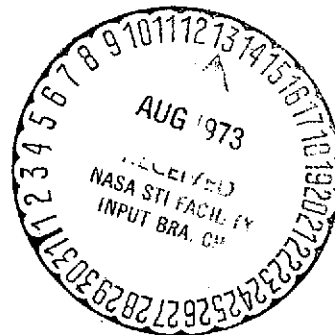
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A Study Prepared for

National Aeronautics and Space Administration  
under Contract NAS8-28516

Prepared by

Dr. Earl H. Gale, Jr.  
General Electric Company  
Aerospace Electronic Systems Department  
Utica, New York



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## SECTION I

### INTRODUCTION

This final report has been prepared by the General Electric Company, Aerospace Electronic Systems Department, Utica, New York under contract NAS8-28516. The report documents the results of a thermal spreading resistance data generation technique study. The method developed is discussed in detail, illustrative examples given, and the resulting computer program is included.

## SECTION II

### BACKGROUND

#### A. GENERAL

"Thermal spreading resistance" is defined as the conductive thermal resistance between a source region and a sink region in a solid where the geometry is such as to preclude one dimensional heat flow.

Knowledge of thermal spreading resistance is needed in two aerospace engineering areas. These are the thermal design of electronic components or equipments and in the prediction and control of thermal contact resistance.

##### 1. Importance To The Design Of Electronic Components and Equipments

The thermal analysis of a power semiconductor or integrated circuit can be reduced to the problem of determining the appropriate spreading and bonding thermal resistances. As an example, the problem of calculating the junction-to-case thermal resistance of a semiconductor bonded to a substrate which is bonded in a metal case will be considered. Figure 1 illustrates this problem.

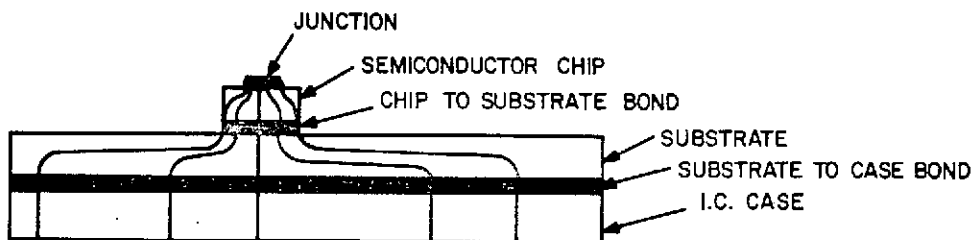


Figure 1. Semiconductor in an Integrated Circuit

Heat is generated in a region of known size, the junction region of the semiconductor. The first, and most significant, spreading resistance of interest occurs between the junction and the opposite face of the silicon chip. The next thermal resistance of interest is that across the bond between chip and substrate. It is of significance that these thermal resistances are not independent although many thermal designers, under the pressures of a design schedule, have treated them as such. The thermal conductance of the bond proper can vary several thousand-fold depending on the use of a metallic or nonmetallic bonding material. The resistance to heat flow between the semiconductor chip bond region and the rear of the substrate represents a second spreading resistance, etc. In a typical integrated circuit package the entire bottom region of the substrate would not be available as a sink for a single semiconductor chip due to the presence of other heat dissipating chips. It is usually possible to estimate the effective sink region on the rear of the substrate from considerations of symmetry or because it exceeds dimensions which appreciably affect the thermal spreading resistance. In those few cases where interactions must be considered, the key analytical tool is superposition; Green's function approach

may also be employed to advantage. For example, see reference 1 and the discussion beginning on page 37 of this report.

The importance of being able to predict thermal spreading resistances in single and multi-layered material in the evaluation of the thermal design of semiconductor or integrated circuits has been shown. Spreading thermal resistances are important in other electrical devices such as phased array antenna elements, Peltier coolers, Seebeck generators and many devices which utilize conductive heat transfer.

## B. PREDICTION AND CONTROL OF THERMAL CONTACT RESISTANCE

The resistance to heat flow between two mating (touching, as in a joint) pieces of metal is called thermal contact resistance. When the actual microscopic regions of contact between two mating surfaces are examined, it is found that metal-to-metal contact occurs in small discrete regions where the asperities or microscopic protuberances make contact. References 2 and 3 describe this model of contact in great detail. Figure 2 illustrates this contact model.

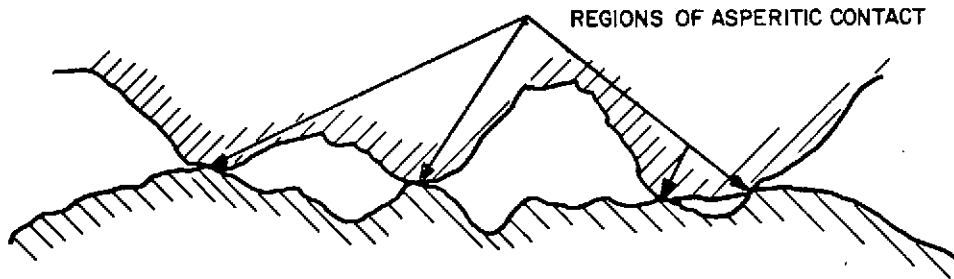


Figure 2. Microscopic View of the Joint of Contacting Pieces of Metal

The heat flow to and from a region of asperitic contact into the contacting proper is seen to be of the "spreading" type. In fact, the effective thermal contact resistance of any contact may be considered as the sum of the parallel microscopic spreading resistances in the contacts themselves. References 2 and 3 above deal largely with isentropic contacts in which the thermal conductivity within the bodies of both contacts is uniform.

Analysis has shown that the bulk of the spreading resistance occurs close to the region of actual asperitic contact and that the spreading resistance in any region varies inversely with the thermal conductivity of the material. Figures 3 and 4 illustrate the first of these points. Figure 3, drawn to scale, shows the equipotential lines about a circular contact region each drawn to show one-tenth of the total spreading resistance between the circular source region and the body of a very large contact. It is seen that half of this total resistance occurs within one contact radius from the circular contact or source region and 80 percent occurs within three contact radii. Figure 4 illustrates these relationships. Figures 3 and 4 are taken from reference 4.

The thermal conductivity of contact close to the surface is of such importance that even a thin 45 Angstrom thick layer of oxide on an aluminum contact can contribute measurably to the thermal contact resistance of an aluminum contact. This has been shown by Gale, reference 4.

Mikic and Carnasciali, reference 5, have utilized the above principle to enhance thermal contact conductance by plating materials of higher conductivity on the contacting faces of a



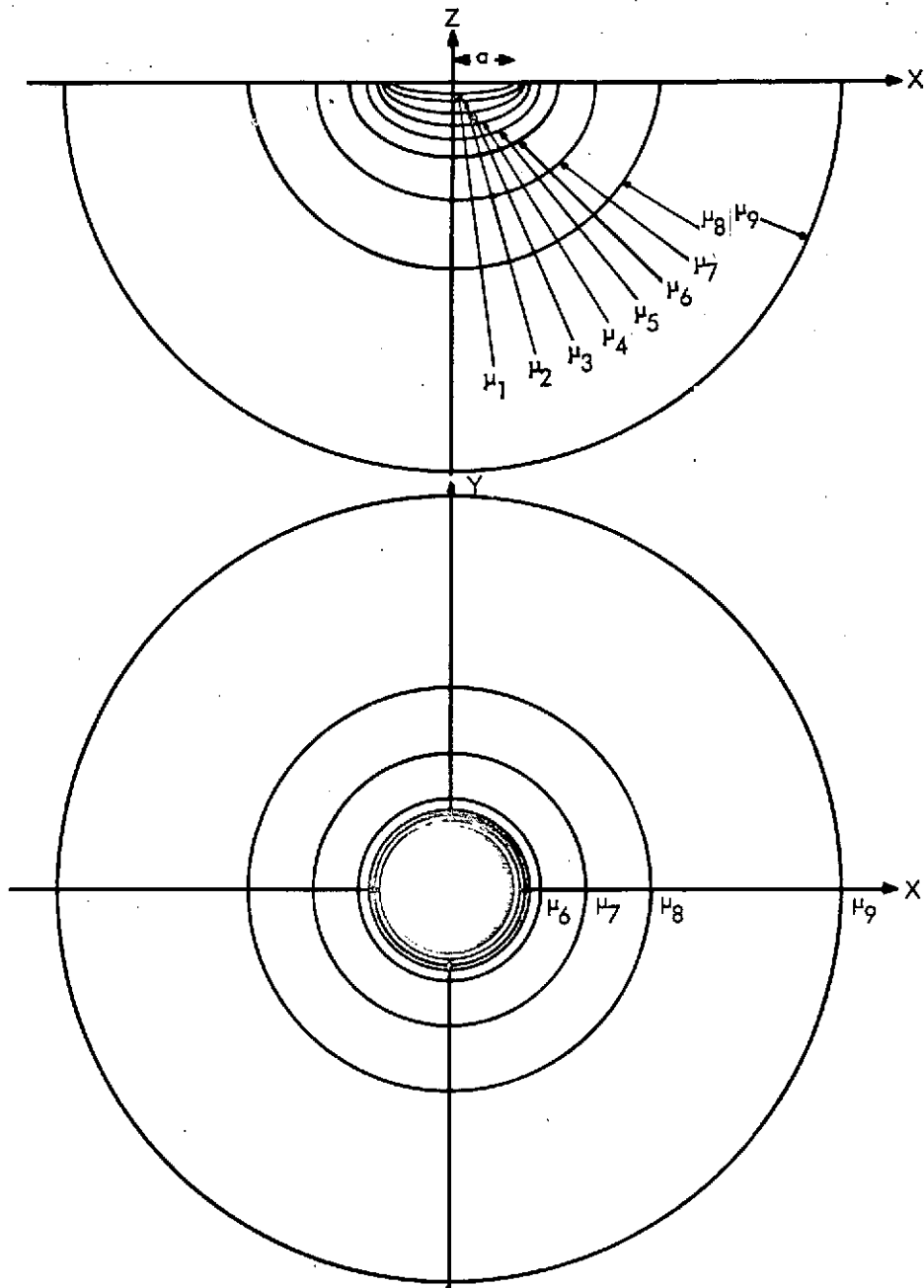


Figure 3. Temperature Profiles Described by Holm's Equation for Isothermal Circular Source on a Semi-infinite Slab

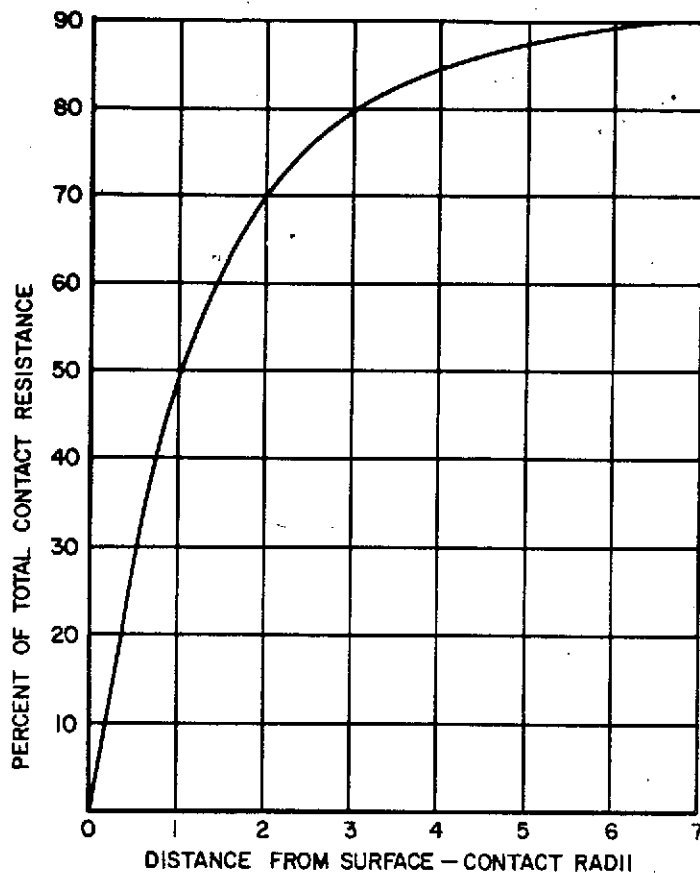


Figure 4. Percent of Total Constriction Resistance for a Single Isothermal Circular Source on a Semi-infinite Slab as a Function of Distance into Body of Contact

metallic joint. They have attempted an analysis of spreading resistance from a circular contact into a contact composed of two layers of materials with different conductivities. An exact boundary value solution of this basic problem has proven too difficult as no mathematical function has been found which will satisfy the boundary conditions between the plating and the body materials.

Professor C. J. Moore, Jr.<sup>1</sup> in his discussion printed at the end of reference 5 felt this two layered spreading resistance problem could best be handled by a "well-conditioned finite difference computer code." Mikic and Carnasciali then question the economic feasibility of such calculations.

Attempts by the author of this study to solve the two layer thermal spreading resistance problem using a finite difference approach utilizing Gauss-Seidel iteration have shown the cost of digital computer calculation to be great.

### SECTION III

#### THEORY

##### A. GENERAL

The governing differential equation for the thermal spreading resistance problem is Poisson's equation. For those spreading resistance problems that are two-dimensional<sup>2</sup> or may be reduced to two-dimensional problems, the equation is:

$$\frac{\partial^2 T}{\partial x^2} + \frac{\partial^2 T}{\partial y^2} = q_t''' \quad (1)$$

Consider a rectangular field subdivided into rectangular subregions as illustrated in Figure 5. The heat balance equation describing the heat flow among element  $m, n$  and its four principal neighbors is:

$$(T_{m,n} - T_{m,n+1}) H_{m,n} + (T_{m,n} - T_{m-1,n}) V_{m,n} + (T_{m,n} - T_{m,n-1}) H_{m,n-1} \\ + (T_{m,n} - T_{m+1,n}) V_{m+1,n} = q_{m,n} \quad (2)$$

where:

$T$  is temperature

$q'''$  heat generated per unit volume

$x, y, z$  are spatial coordinates

$H, V$  are horizontal and vertical conductances, respectively

$q_{m,n}$  heat generated in mode  $m, n$

The convention for the horizontal and vertical conductances used is shown in Figure 6.

Each of the following observations below will be helpful in understanding the discussion which follows:

- (1) When any temperature  $T_{m,n}$  is known (e.g., as a boundary condition), it will affect equation  $m, n$  by yielding a term  $q_{m,n}'$ , which is subtracted from the right hand side of equation (2) where  $q_{m,n}'$  is:

$$q_{m,n}' = T_{m,n} (H_{m,n} + V_{m,n} + H_{m,n-1} + V_{m+1,n}) \quad (3)$$

<sup>1</sup>Associate Professor of Mechanical and Aerospace Engineering, North Carolina State University, Raleigh, N.C.

<sup>2</sup>The method developed is applicable to three-dimensional problems as will be shown later in the report.

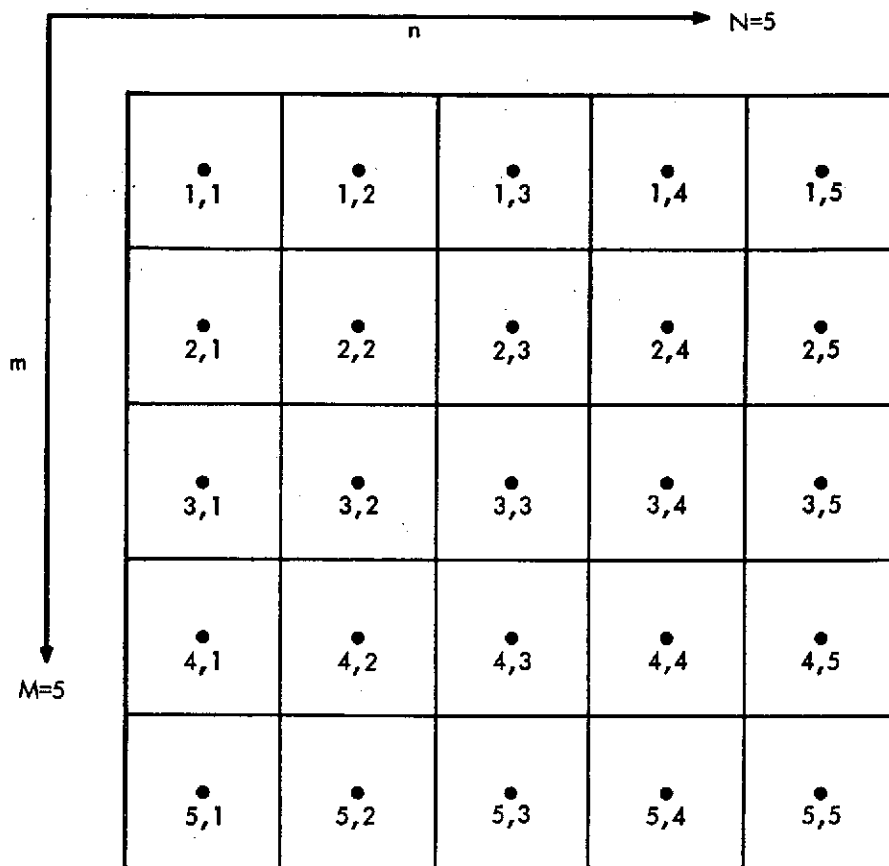


Figure 5. Rectangular Field Divided into 25 Finite Elements

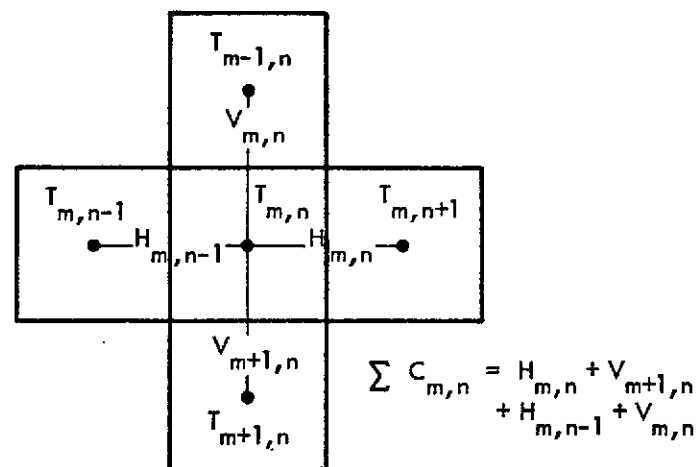


Figure 6. Nomenclature for Nodal Interconductances

(2) If the original field is divided into M rows and N columns, and further if  $M = N$ , then:

- (a) There will be  $N^2$  linear equations.
- (b) There will be not more than  $N^2$  unknowns (fewer if some temperatures are initially prescribed).
- (c) There can be as many different and distinct nodal conductances as there are interconnections between nodes.

Now, if the system of linear finite difference equations is written in matrix form (taking the nodes of Figure 5 into consideration) from left to right, top row to bottom row, as in reading English, a coefficient matrix results that has a pattern characteristic for field problems described by Poisson's or LaPlace's equations. This pattern is illustrated in Figure 7.

It was noted by Karlqvist (Reference 6) that the matrix in Figure 7 may be partitioned as shown. It can be seen that each of the submatrices is  $N \times N$  and the coefficient matrix is  $N^2 \times N^2$  where the original finite element matrix was  $N \times N$  in size.

#### B. DERIVATION OF AN EFFICIENT TECHNIQUE FOR EXACT SOLUTION OF THIS SYSTEM OF EQUATIONS

Defining the sub-matrices shown in Figure 7 as follows:

$$\begin{bmatrix} B_1 & C_1 & 0 & 0 & 0 \\ A_2 & B_2 & C_2 & 0 & 0 \\ 0 & A_3 & B_3 & C_3 & 0 \\ 0 & 0 & A_4 & B_4 & C_4 \\ 0 & 0 & 0 & A_5 & B_5 \end{bmatrix} \begin{bmatrix} T_1 \\ T_2 \\ T_3 \\ T_4 \\ T_5 \end{bmatrix} = \begin{bmatrix} Q_1 \\ Q_2 \\ Q_3 \\ Q_4 \\ Q_5 \end{bmatrix}$$

Figure 8. System Of Submatrices In Matrix Notation

Expanding the partitioned matrices (Figure 8) into a system of equations, having normalized each equation with respect to the diagonal element:

$$\begin{array}{cccccc} T_1 & B_1^{-1}C_1T_2 & 0 & 0 & 0 & = B_1^{-1}Q_1 \\ B_2^{-1}A_2T_1 & T_2 & B_2^{-1}C_2T_3 & 0 & 0 & = B_2^{-1}Q_2 \\ 0 & B_3^{-1}A_3T_2 & T_3 & B_3^{-1}C_3T_4 & 0 & = B_3^{-1}Q_3 \\ 0 & 0 & B_4^{-1}A_4T_3 & T_4 & B_4^{-1}C_4T_5 & = B_4^{-1}Q_4 \\ 0 & 0 & 0 & B_5^{-1}A_5T_4 & T_5 & = B_5^{-1}Q_5 \end{array}$$

Upon redefining constants in the following manner:

$$B_2^{-1}A_2 \equiv -B_2, \quad B_2^{-1}C_2 \equiv -A_2, \quad \text{and} \quad B_2^{-1}Q_2 \equiv C_2, \text{ etc.}$$

**Figure 7. System of Equations in Matrix Notation**

the general equation has the form:

$$-B_i T_{i-1} + T_i - A_i T_{i+1} = C_i \quad (4)$$

The first equation can be solved for  $T_1$ :

$$T_1 = C_1 + A_1 T_2 \quad (5)$$

and the  $i$ th for  $T_i$ :

$$T_i = C_i + A_i T_{i+1} + B_i T_{i-1} \quad (6)$$

The goal is to find a recursion relationship built upon successive substitutions, which provides a solution for the  $i$ th unknown in terms of the  $(i+1)$ th. That is:

$$T_i = A_i' T_{i+1} + B_i' \quad (7)$$

Examining equation (5) for  $T_1$  above, it can be seen that:

$$A_1' = A_1 \text{ and } B_1' = C_1$$

The equation for  $T_2$  is:

$$T_2 = C_2 + A_2 T_3 + B_2 T_1 \quad (8)$$

which, when written in terms of the equation for  $T_1$ , becomes:

$$T_2 = [I - B_2 A_1]^{-1} A_2 T_3 + [I - B_2 A_1]^{-1} [C_2 + B_2 B_1'] \quad (9)$$

The general coefficients found in this manner become

$$A_i' = [I - B_i A_{i-1}']^{-1} A_i$$

and

$$B_i' = [I - B_i A_{i-1}']^{-1} [B_i B_{i-1}' + C_i]$$

Therefore

$$T_i = A_i' T_{i+1} + B_i' \quad (10)$$

The temperature matrices (columns) are found starting at the  $N$ th row by making

$$T_N = B_N' \quad (11)$$

$A_N = 0$  as a boundary condition results in modification of  $C_N$  above [ see equation (3) ].

The system of equations has been solved by operating on  $3\sqrt{N} - 2$  submatrices, each of which is the square root of the size of the original  $N \times N$  coefficient.  $3\sqrt{N}$  inversions of these

submatrices are required. The total number of multiplications (an indication of the effort) required during solution is:

$$\text{No. of Multiplications} = 3N^2 + N^{3/2} - N + N^{1/2} \quad (12)$$

This may be compared against other direct methods (see Ref. 7):

<u>Method</u>	<u>Number of Multiplications Required during Solution</u>
Gaussian Elimination	$\frac{1}{3} N^3 + N^2 - \frac{1}{3} N$
Jordan	$\frac{1}{2} N^3 + N^2 - \frac{1}{2} N$
Doolittle	$\frac{1}{3} N^3 + N^2 - \frac{1}{3} N$
Cholesky	$\frac{1}{6} N^3 + \frac{3}{2} N^2 + \frac{1}{3} N$

Cornock's method (Ref. 8), a triangulation type, also makes use of the characteristic pattern of submatrices which results during a finite difference solution for fields described by Poisson's equation. When the field properties are homogeneous and isentropic, Cornock's method is very powerful since only one of the above submatrices of order  $\sqrt{N}$  need be inverted. However, for the general solution of the nonhomogeneous field, the number of multiplications required is

$$\frac{13}{2} N^2 - \frac{3}{2} N^{3/2} - 2N - 5 \quad (13)$$

A serious drawback to Cornock's method is that it does not lend itself to ready general programming for matrices of variable size as does the method described in this report.

That equation (12) is indicative of the computer effort required for solution has been substantiated in practice. Figure 9 shows the variation in cost realized in the solution of very large matrices using the method developed in this report. Also, a strong feature of this method is that very large systems of equations, e.g., 2500, can be conveniently handled in a direct solution.

The FORTRAN Y program contained in the Appendix was used on a Honeywell 630 computer in generating the dollar costs shown in Figure 9. Out-of-core storage of submatrices was utilized for very large systems.

### C. APPLICABILITY OF TECHNIQUE TO THREE-DIMENSIONAL PROBLEMS

The technique discussed above is suited to the solution of field problems having three or more dimensions. Figure 10 illustrates the characteristic pattern of the coefficient matrix for a three dimensional finite element array. It is seen that the submatrices are  $\sqrt{3N}$  in size. The same block tridiagonal pattern of submatrices is seen to occur as in the two-dimensional case so the derivation above for the technique of solution for two dimensional matrices is still applicable. Thus, although the BASIC and FORTRAN Y program presented later in this report are written for two-dimensional problems, little revision of these programs is required to handle three dimensional programs. Since the submatrices are  $\sqrt{3N}$  rather than the  $\sqrt{2N}$  in size, the technique is even more powerful for three dimensional problems. The number of multiplications



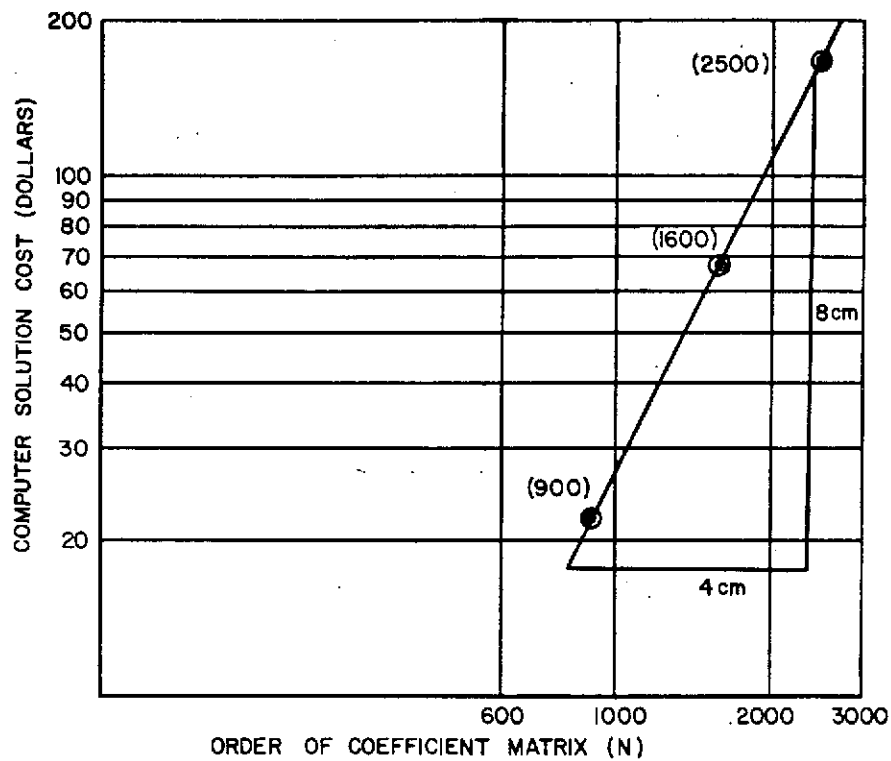
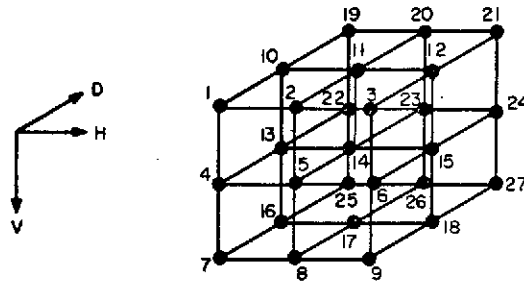


Figure 9. Cost of Computation vs Size of Coefficient Matrix

required for solution of the three-dimensional problem is a function of  $N^{4/3}$  as opposed to  $N^2$  for the two dimensional array where  $N$  is the order of the coefficient matrix.



		N																										
M		1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25	26	27
	1	$\Sigma$	H	0	V	0	0	0	0	0	D	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	2	H	$\Sigma$	H	0	V	0	0	0	0	0	D	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	3	0	H	$\Sigma$	0	0	V	0	0	0	0	0	D	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	4	V	0	0	$\Sigma$	H	0	V	0	0	0	0	0	D	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	5	0	V	0	H	$\Sigma$	H	0	V	0	0	0	0	0	D	0	0	0	0	0	0	0	0	0	0	0	0	0
	6	0	0	V	0	H	$\Sigma$	0	0	V	0	0	0	0	0	D	0	0	0	0	0	0	0	0	0	0	0	0
	7	0	0	0	V	0	0	$\Sigma$	H	0	0	0	0	0	0	0	D	0	0	0	0	0	0	0	0	0	0	0
	8	0	0	0	0	V	0	H	$\Sigma$	H	0	0	0	0	0	0	0	D	0	0	0	0	0	0	0	0	0	0
	9	0	0	0	0	0	V	0	H	$\Sigma$	0	0	0	0	0	0	0	0	D	0	0	0	0	0	0	0	0	0
	10	D	0	0	0	0	0	0	0	0	$\Sigma$	H	0	V	0	0	0	0	0	D	0	0	0	0	0	0	0	0
	11	0	D	0	0	0	0	0	0	0	H	$\Sigma$	H	0	V	0	0	0	0	0	D	0	0	0	0	0	0	0
	12	0	0	D	0	0	0	0	0	0	0	H	$\Sigma$	0	0	V	0	0	0	0	0	D	0	0	0	0	0	0
	13	0	0	0	D	0	0	0	0	0	V	0	0	$\Sigma$	H	0	V	0	0	0	0	0	D	0	0	0	0	0
	14	0	0	0	0	D	0	0	0	0	0	V	0	H	$\Sigma$	H	0	V	0	0	0	0	0	D	0	0	0	0
	15	0	0	0	0	0	D	0	0	0	0	0	V	0	H	$\Sigma$	0	0	V	0	0	0	0	0	D	0	0	0
	16	0	0	0	0	0	0	D	0	0	0	0	0	V	0	0	$\Sigma$	H	0	0	0	0	0	0	0	D	0	0
	17	0	0	0	0	0	0	0	D	0	0	0	0	0	V	0	H	$\Sigma$	H	0	0	0	0	0	0	0	D	0
	18	0	0	0	0	0	0	0	0	D	0	0	0	0	0	V	0	H	$\Sigma$	0	0	0	0	0	0	0	0	D
	19	0	0	0	0	0	0	0	0	0	D	0	0	0	0	0	0	0	$\Sigma$	H	0	V	0	0	0	0	0	0
	20	0	0	0	0	0	0	0	0	0	0	D	0	0	0	0	0	0	H	$\Sigma$	H	0	V	0	0	0	0	0
	21	0	0	0	0	0	0	0	0	0	0	0	D	0	0	0	0	0	0	H	$\Sigma$	0	0	V	0	0	0	0
	22	0	0	0	0	0	0	0	0	0	0	0	0	D	0	0	0	0	V	0	0	$\Sigma$	H	0	V	0	0	0
	23	0	0	0	0	0	0	0	0	0	0	0	0	0	D	0	0	0	0	V	0	H	$\Sigma$	H	0	V	0	0
	24	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	D	0	0	0	V	0	H	$\Sigma$	0	0	V	0
	25	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	D	0	0	0	0	V	0	0	$\Sigma$	H	0	0
	26	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	D	0	0	0	0	V	0	H	$\Sigma$	H	0
	27	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	D	0	0	0	0	V	0	H	$\Sigma$

T <sub>1</sub>	Q <sub>1</sub>
T <sub>2</sub>	Q <sub>2</sub>
T <sub>3</sub>	Q <sub>3</sub>
T <sub>4</sub>	Q <sub>4</sub>
T <sub>5</sub>	Q <sub>5</sub>
T <sub>6</sub>	Q <sub>6</sub>
T <sub>7</sub>	Q <sub>7</sub>
T <sub>8</sub>	Q <sub>8</sub>
T <sub>9</sub>	Q <sub>9</sub>
T <sub>10</sub>	Q <sub>10</sub>
T <sub>11</sub>	Q <sub>11</sub>
T <sub>12</sub>	Q <sub>12</sub>
T <sub>13</sub>	Q <sub>13</sub>
T <sub>14</sub>	Q <sub>14</sub>
T <sub>15</sub>	Q <sub>15</sub>
T <sub>16</sub>	Q <sub>16</sub>
T <sub>17</sub>	Q <sub>17</sub>
T <sub>18</sub>	Q <sub>18</sub>
T <sub>19</sub>	Q <sub>19</sub>
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T <sub>25</sub>	Q <sub>25</sub>
T <sub>26</sub>	Q <sub>26</sub>
T <sub>27</sub>	Q <sub>27</sub>

WHERE  $\Sigma_M = -\Sigma \cdot (V_m + H_m + D_m)$

Figure 10. Matrix Representation of System of Equations Describing Three-Dimensional Field Showing Pattern Established by Submatrices of Coefficient Matrix

## SECTION IV

### ILLUSTRATIVE PROBLEM AND PROGRAM

A sample thermal spreading resistance problem will be solved to illustrate the technique presented in Section II. The computer program used in the problem is written in BASIC language. A general version of the same program written in FORTRAN Y is included in the Appendix.

#### A. DESCRIPTION OF SAMPLE PROBLEM

The thermal spreading resistance problem to be considered is depicted in Figure 11. Heat is uniformly generated in a plane circular region of radius  $a$  and flows to a circular sink of radius  $b$  both concentric with, and parallel to, the source region a distance  $H$  away in a conductive medium. The conductive medium is divided into two regions of different conductivity. An exact closed form solution of this problem has not been found.

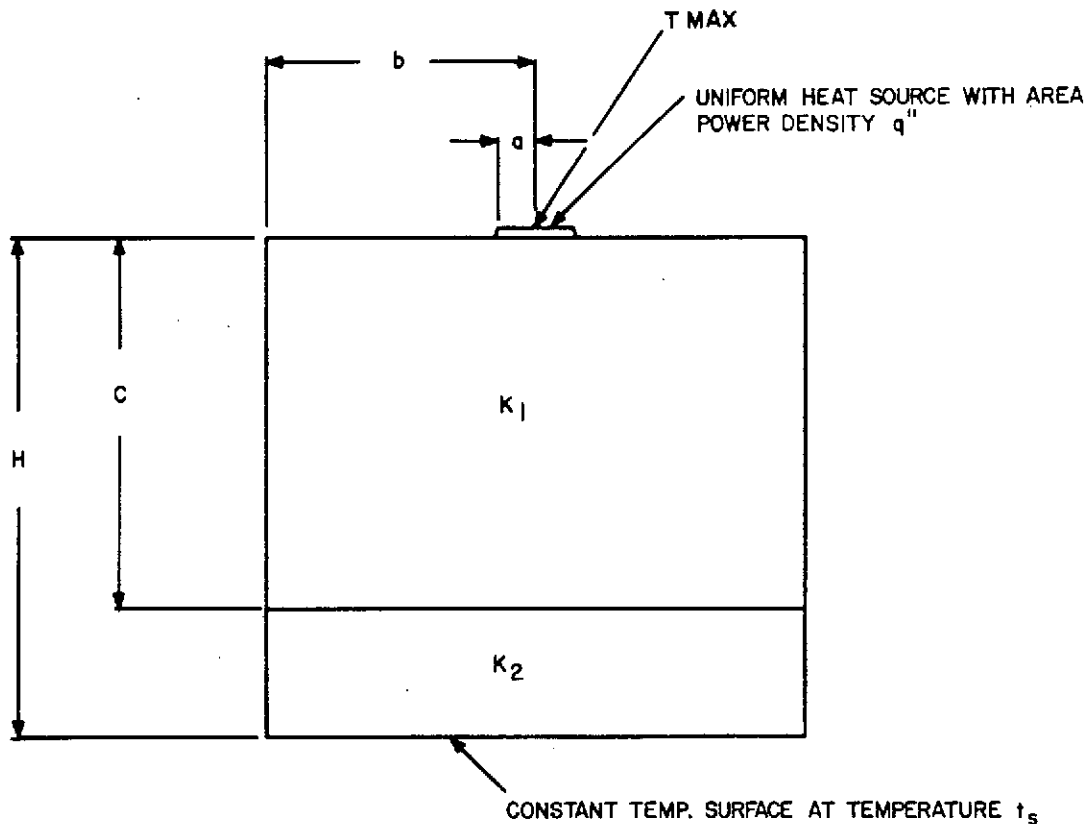


Figure 11. Mathematical Model for Spreading Resistance Nomographs

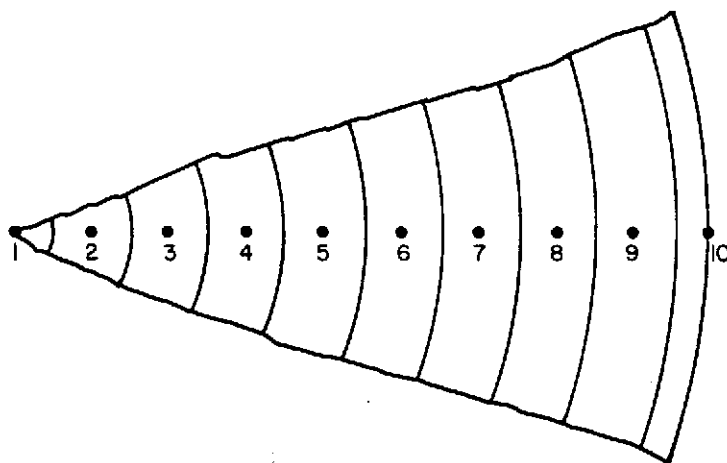
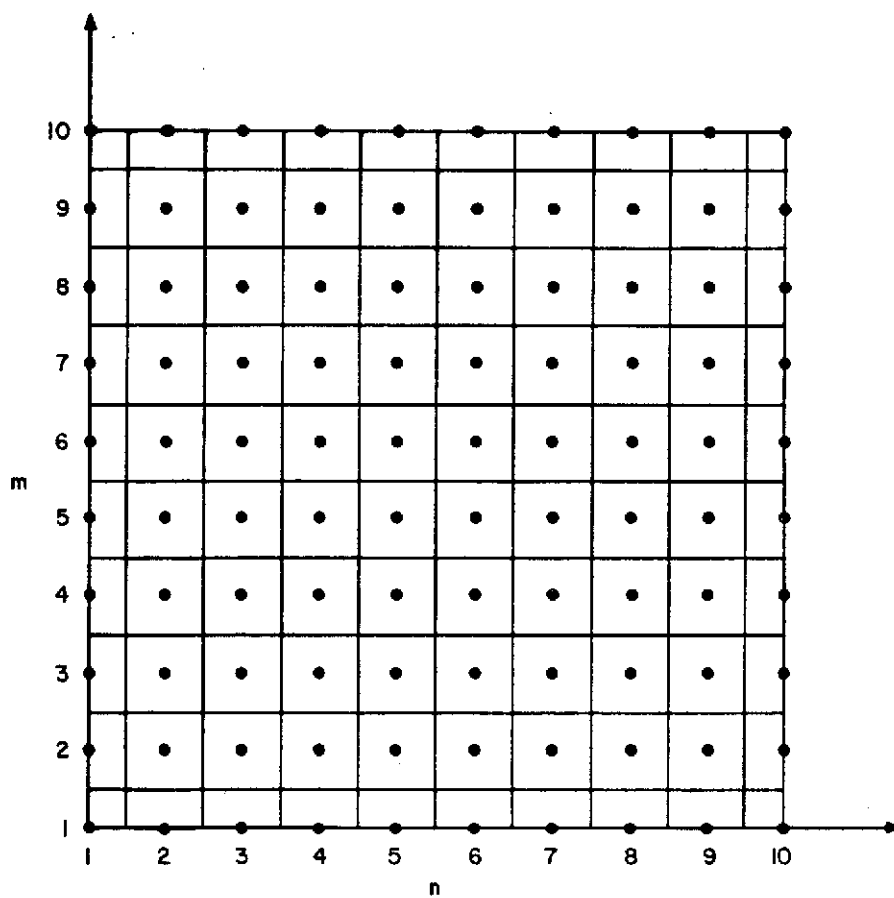


Figure 12. Nodal Pattern for Sample Problem

Ratios of geometries and conductivities used in the generation of sample data are summarized below. All data is generated and presented in nondimensional parameters.

Parameter	Number of Values	Parametric Values
a/b	6	0.111, 0.222, 0.166, 0.551, 0.388, 0.5
H/b	6	0.1, 0.2, 0.5, 1, 2, 5
C/H	5	0.1, 0.2, 0.3, 0.5,
K1/K2	5	0.01, 0.1, 0.2, 0.5, 1

The above three-dimensional problem can be viewed as two-dimensional since all heat flow within the cylinder is in the axial and radial directions. Further, there is symmetry about the axis of the cylinder.

Figure 12 shows the arrangement of finite elements used in the illustrative data generation program.

## B. CALCULATION OF NODAL CONDUCTANCES

The convention used for the nodal conductances was that the vertical conductance  $V_{(m,n)}$  associated with each node was that in the upward direction and the horizontal conductance  $H_{(m,n)}$  was that connecting with the node on the right. This is illustrated in Figure 13.

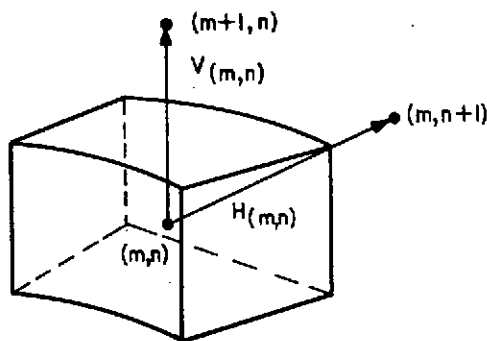


Figure 13. Convention for Nodal Conductances

The calculation of conductances is straightforward for all modes except for those nodes of horizontal conductance lying on the axis of the cylinder, i.e.,  $n = 1$ . The horizontal conductance of this inner node was approximated by using the exact solution of Jacob (Ref. 9) for two-dimensional heat flow within a cylinder having uniformly distributed internal heat generation for the difference between the mean temperature of the cylinder and the outside surface with radial flow.

The conductances of all other nodes could be calculated in an exact manner using calculus. General expressions for the M, Nth nodal conductances in terms of M, N were developed and used in the sample problem to facilitate changing the program to allow the use of different numbers of finite elements.

### C. DETAILED DESCRIPTION OF ILLUSTRATIVE PROGRAM

Figure 14 shows the computer program for the illustrative program. The major steps in the program are described below.

<u>Line No.</u>	<u>Description</u>
10-60	Dimensioning symbols will be defined as used in this program. The same symbol may be redefined several times.
70	$P = \pi$
80	C1 is that part of the horizontal thermal resistance of nodes 10, 1 and 1, 1 between the nodal point and the surface of these nodes. (See discussion above concerning Jacob's formula.)
90	Expressions for entire horizontal resistance between nodes 10, 1 and 10, 2 as well as 1, 1 and 1, 2.
110	H is the horizontal conductance.
160	V is the vertical conductance to node above.
200	Generalized expression for horizontal conductance for most modes, m, n.
210	Generalized expression for vertical conductance for most modes, m, n.
290, 320	Entering adiabatic boundary conditions at top and sides.
380-460	A9 is the radius of the heat generating region.
470	Calculation and print of a/b (see Figure 11).
480-250	Entering uniform heat input in the circular region described by A9. Use is made of the area dependence share by vertical conductance and heat input.
530-651	Setting of H/b (see Figure 11).
680-690	Adjustment of horizontal and vertical conductance for H/b.
720-801	Setting of C/H (see Figure 11).
810-971	Establishment and assignment of values for K1/K2 (see Figure 11).
990, 1000	Optional printout of $H_{(m,n)}$ and $V_{(m,n)}$
1010-1220	Generation of coefficient matrix.
1010	M is row number of physical nodal pattern.
1080	Sets subdiagonal and superdiagonal in the coefficient matrix (line arrays W immediately either side of the main diagonal) to zero (see Figure 15d).

(Continued on page 25)

```

1PRINT"  A/B      ","H/B      ","C/H      ","K1/K2      ","Y"
2 PRINT
10 DIM H(12,12),V(12,12),T(12,12),G(10,10)
20 DIM X(10,10),Y(10,10),W(10,10),Z(10,10)
30 DIM A(10,10),B(10,10),D(10,10),E(10,10)
40 DIM F(10,10),G(10,10),I(10,10),J(10,10),K(10,10)
50 DIM L(10,10),M(10,10),N(10,10),O(10,10),P(10,10)
60 DIM R(10,10),S(10,10),U(10,10)
70 P=3.14159265
80 C1=.125/P
90 R1=C1+(LOG(2))/(2*P)
100 R2=R1/2
101 FOR N4=4 TO 5
102 FOR N3=1 TO 5
103 FOR N2=1 TO 6
104 FOR N1=1 TO 9
110 H(1,1)=H(10,1)=1/R1
120 FOR M=2 TO 9
130 H(M,1)=2*H(1,1)
140 NEXT M
150 FOR M=1 TO 10
160 V(M,1)=P/2
170 NEXT M
180 FOR M=1 TO 10
190 FOR N=2 TO 10
200 H(M,N)=1/(1/(4*P)*LOG(N/(N-1)))
210 V(M,N)=P*4*(N-1)
220 IF M>1.1 THEN 240
230 H(1,N)=.5*H(1,N)
240 H(10,N)=.5*H(10,N)
250 V(M,10)=P*(4*N-5)/2
260 NEXT N
270 NEXT M
280 FOR M=1 TO 10
290 H(M,10)=0
300 NEXT M
310 FOR N=1 TO 10
320 V(1,N)=0
330 NEXT N
380 IF N1=1 THEN 2660
390 IF N1=5 THEN 2660
400 IF N1=7 THEN 2660
410 IF N1=9 THEN 2660
420 A9=1
430 IF N1<2 THEN 470
440 A9=2*N1-1
450 IF N1<10 THEN 470
460 A9=18
470 PRINT USING 471,A9/18,
471: ##.##
480 C(1,1)=V(2,1)*2.00000
490 IF N1=1 THEN 530
491 FOR N=2 TO 10
492 C(N,1)=0

```

Figure 14. Computer Program for Illustrative Example  
(Sheet 1 of 6)

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```

493 NEXT N
500 FOR N=1 TO N1
510 C(N,1)=V(2,N)*2.0000
520 NEXT N
530 H1=.1
540 IF N2<2 THEN 650
550 H1=.2
560 IF N2<3 THEN 650
570 H1=.5
580 IF N2<4 THEN 650
590 H1=1
600 IF N2<5 THEN 650
610 H1=2
615 IF N2< 6 THEN 650
620 H1=5
630 IF N2<7 THEN 650
640 H1=10
650 PRINT USING 651,H1,
651:#####.##
660 FOR M=1 TO 10
670 FOR N=1 TO 10
680 V(M,N)=V(M,N)/H1
690 H(M,N)=H(M,N)*H1
700 NEXT N
710 NEXT M
720 C1=1
730 IF N3<2 THEN 800
740 C1=2
750 IF N3<3 THEN 800
760 C1=3
770 IF N3<4 THEN 800
780 C1=5
785 IF N3<5 THEN 800
790 C1=7
800 PRINT USING 801,C1/10,
801:#####.##
810 K2=1
820 IF N4<2 THEN 910
830 K2=2
840 IF N4< 3 THEN 910
850 K2=5
860 IF N4<4 THEN 910
870 K2=10
880 IF N4<5 THEN 910
890 K2=100
910 FOR M=C1+1 TO 10
920 FOR N=1 TO 10
930 V(M,N)=V(M,N)*K2
940 H(M,N)=H(M,N)*K2
950 NEXT N
960 NEXT M
970 PRINT USING 972,1/K2,
972:#####.##
980 GO TO 1010

```

Figure 14. Computer Program for Illustrative Example  
(Sheet 2 of 6)



```
990 MAT PRINT H;
1000 MAT PRINT V;
1010 FOR M=1 TO 10
1020 MAT X=ZER
1030 MAT Y=ZER
1040 MAT W=ZER
1050 FOR N=1 TO 10
1060 IF N=1 THEN 1090
1070 IF N=10 THEN 1090
1080 W(N,N-1)=W(N,N+1)=0
1090 IF N<2 THEN 1110
1100 W(N,N-1)=-H(M,N-1)
1110 IF N> 9 THEN 1130
1120 W(N,N+1)=-H(M,N)
1130 X(N,N)=-V(M+1,N)
1140 Y(N,N)=-V(M,N)
1150 C3=0
1160 IF N=1 THEN 1180
1170 C3=W(N,N-1)
1180 IF N=10 THEN 1200
1190 C3=C3+W(N,N+1)
1200 W(N,N)=C3+X(N,N)+Y(N,N)
1210 W(N,N)=-W(N,N)
1220 NEXT N
1230 MAT Z= INV(W)
1240 MAT W= Z*X
1250 MAT T=(-1)*W
1260 MAT W=T*(1)
1270 MAT X= Z*Y
1280 MAT T=ZER
1290 MAT T=(-1)*X
1300 MAT X=T*(1)
1310 IF M<>1 THEN 1350
1320 MAT A=Z*C
1330 MAT C=ZER
1340 MAT B=W*(1)
1350 IF M<>2 THEN 1380
1360 MAT C=X*(1)
1370 MAT D=W*(1)
1380 IF M<>3 THEN 1410
1390 MAT E=X*(1)
1400 MAT F=W*(1)
1410 IF M<>4 THEN 1440
1420 MAT G=X*(1)
1430 MAT I=W*(1)
1440 IF M<>5 THEN 1470
1450 MAT J=X*(1)
1460 MAT K=W*(1)
1470 IF M<>6 THEN 1500
1480 MAT L=X*(1)
1490 MAT M=W*(1)
1500 IF M<>7 THEN 1530
1510 MAT N=X*(1)
1520 MAT O=W*(1)
```

Figure 14. Computer Program for Illustrative Example  
(Sheet 3 of 6)

# GE RECOMM GE RECOMM GE RECOMM GE RECOMM

```

1530 IF M<>8 THEN 1560
1540 MAT P=X*(1)
1550 MAT Q=W*(1)
1560 IF M<>9 THEN 1590
1570 MAT R=X*(1)
1580 MAT S=W*(1)
1590 IF M<10 THEN 1630
1600 MAT T=ZER
1610 MAT T=X*(1)
1620 MAT U=W*(1)
1630 NEXT M
1640 FOR M=1 TO 10
1650 FOR N=1 TO 10
1660 W(M,N)=X(M,N)=Y(M,N)=Z(M,N)=0
1670 NEXT N
1680 NEXT M
1690 MAT X=C*B
1700 MAT Y=IDN
1710 MAT Z=Y-X
1720 MAT X=INV(Z)
1730 MAT Z=X*D
1740 MAT D=Z*(1)
1750 MAT Z=C*A
1760 MAT C=X*Z
1770 MAT X=E*D
1780 MAT Z=Y-X
1790 MAT X=INV(Z)
1800 MAT Z=X*F
1810 MAT F=Z*(1)
1820 MAT Z=E*C
1830 MAT E=X*Z
1840 MAT X=G*F
1850 MAT Z=Y-X
1860 MAT X=INV(Z)
1870 MAT Z=X*I
1880 MAT I=Z*(1)
1890 MAT Z=G*E
1900 MAT G=X*Z
1910 MAT X=J*I
1920 MAT Z=Y-X
1930 MAT X=INV(Z)
1940 MAT Z=X*K
1950 MAT K=Z*(1)
1960 MAT Z=J*G
1970 MAT J=X*Z
1980 MAT X=L*K
1990 MAT Z=Y-X
2000 MAT X=INV(Z)
2010 MAT Z=X*M
2020 MAT M=Z*(1)
2030 MAT Z=L*J
2040 MAT L=X*Z
2050 MAT X=N*M
2060 MAT Z=Y-X

```

Figure 14. Computer Program for Illustrative Example  
(Sheet 4 of 6)

# COMM GE RECOMM GE RECOMM GE RECOMM

```

2070 MAT X=INV(Z)
2080 MAT Z=X*Q
2090 MAT Q=Z*(1)
2100 MAT Z=N*L
2110 MAT N= X*Z
2120 MAT X=P*Q
2130 MAT Z=Y-X
2140 MAT X=INV(Z)
2150 MAT Z=X*Q
2160 MAT Q=Z*(1)
2170 MAT Z=P*N
2180 MAT P=X*Z
2190 MAT X=R*Q
2200 MAT Z=Y-X
2210 MAT X=INV(Z)
2220 MAT Z=X*S
2230 MAT S=Z*(1)
2240 MAT Z= R*P
2250 MAT R=X*Z
2260 MAT X= T*S
2270 MAT Z=Y-S
2280 MAT X= INV (Z)
2290 MAT Z=X*U
2300 MAT U=Z*(1)
2310 MAT Z=T *R
2320 MAT T=ZER
2330 MAT X= ZER
2340 MAT X=S*T
2350 MAT Y=ZER
2360 MAT Y=X+R
2370 MAT R=Y*(1)
2380 MAT X=Q*Y
2390 MAT Y=X+P
2400 MAT P=Y*(1)
2410 MAT X=Q*Y
2420 MAT Y=X+N
2430 MAT N=Y*(1)
2440 MAT X=M*Y
2450 MAT Y=X+L
2460 MAT L=Y*(1)
2470 MAT X=K*Y
2480 MAT Y=X+J
2490 MAT J=Y*(1)
2500 MAT X=I*Y
2510 MAT Y=X+G
2520 MAT G=Y*(1)
2530 MAT X=F*Y
2540 MAT Y=X+E
2550 MAT E=Y*(1)
2560 MAT X=D *Y

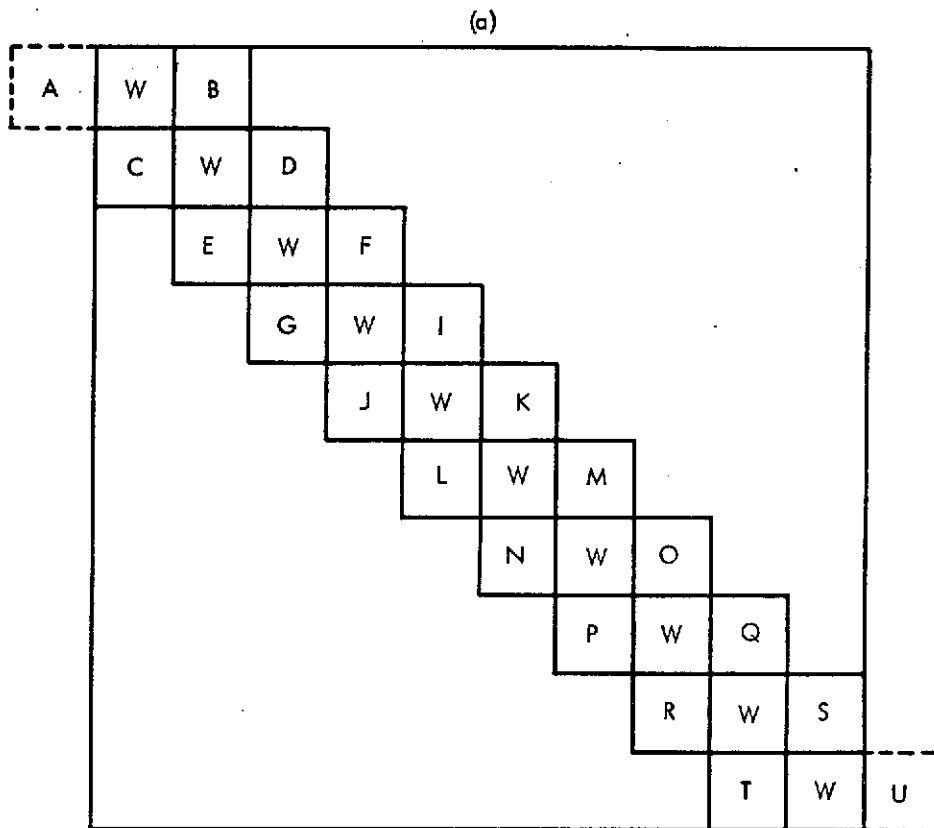
```

Figure 14. Computer Program for Illustrative Example  
(Sheet 5 of 6)

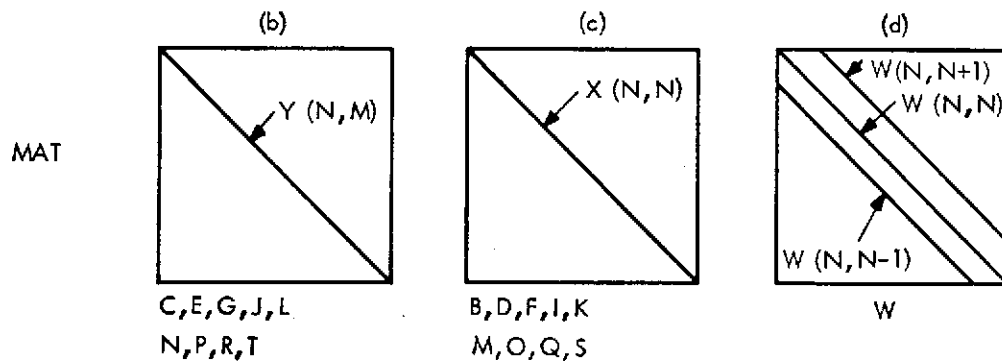
RECOMM GE RE

```
2570 MAT Y=X+C
2580 MAT C=Y*(1)
2590 MAT X=B*Y
2600 MAT Y=X+A
2610 MAT A=Y*(1)
2630 R7=A(1,1)/A9
2640 PRINT USING 2650,R7
2650 #####.##
2660 NEXT N1
2665 PRINT
2670 NEXT N2
2675 PRINT
2680 NEXT N3
2685 PRINT
2690 NEXT N4
2695 PRINT
2700 END
```

Figure 14. Computer Program for Illustrative Example  
(Sheet 6 of 6)



IDENTIFICATION OF SUB-MATRICES OF COEFFICIENT MATRIX



INTERNAL MAKEUP OF THE SUB-MATRICES

Figure 15. Identification and Internal Makeup of Submatrices of Coefficient Matrix

<u>Line No.</u>	<u>Description</u>
1100	Assigns values to first subdiagonal of the coefficient matrix W (see Figure 15d) describing the mth row of the physical nodal pattern.
1120	Assigns values to first subdiagonal of the coefficient matrix W as in line 1100.
1130	Assigns values to the X submatrix (see Figure 15c).
1140	Assigns values to the Y submatrix (see Figure 15b).
1200, 1210	Enters elements down the main diagonal of the W submatrices.
1230	First submatrix manipulation statement.
1240	Normalizes the submatrix to the right of the W matrix diagonal (see Figure 15a).
1270	Normalizes the submatrix to the left of the W matrix (see Figure 15a).
1280	Empties T matrix.
1320-1630	Assigns each of the submatrices, subdiagonal and superdiagonal, mapped by Figure 15a after normalization. Note that matrices X and W are functions of M, the row of the physical nodal pattern.
1640-1680	Clears matrices W, X, Y, Z, so they may be redefined below by entering only nonzero elements.
1690-2250	These steps calculate the recurrence coefficients $A_i'$ and $B_i'$ according to equation (10) of Section II. As these are calculated, the superdiagonal and subdiagonal matrices of Figure 15a are sequentially redefined to be these recurrence coefficients.
2320	This statement enters the boundary condition that the temperatures along the bottom row of the physical matrix are zero.
2330-2610	Using the recurrence relationship developed in 1690-2250, equation (10) is used to calculate the temperatures, one row (of the physical nodal model) at a time. These (column) matrices of temperatures are calculated in the following order (see Figure 15a) and with the following nomenclature: T, R, P; N, L - J, G, E, C, A.
2630	R7 is the temperature of node 1, 1 divided by the radius of the heat source A9, defined in statements 420-460.

#### D. SAMPLE SOLUTIONS

Figure 16 presents the sample solutions of the illustrative problem.  $t_{MAX}$  is the average temperature nodal point 1, 1, see Figure 12. It is obvious that, for these solutions, increasing the number of nodes in the physical model would have the result of increasing the temperature in this hottest element. This was done and the results are discussed below.

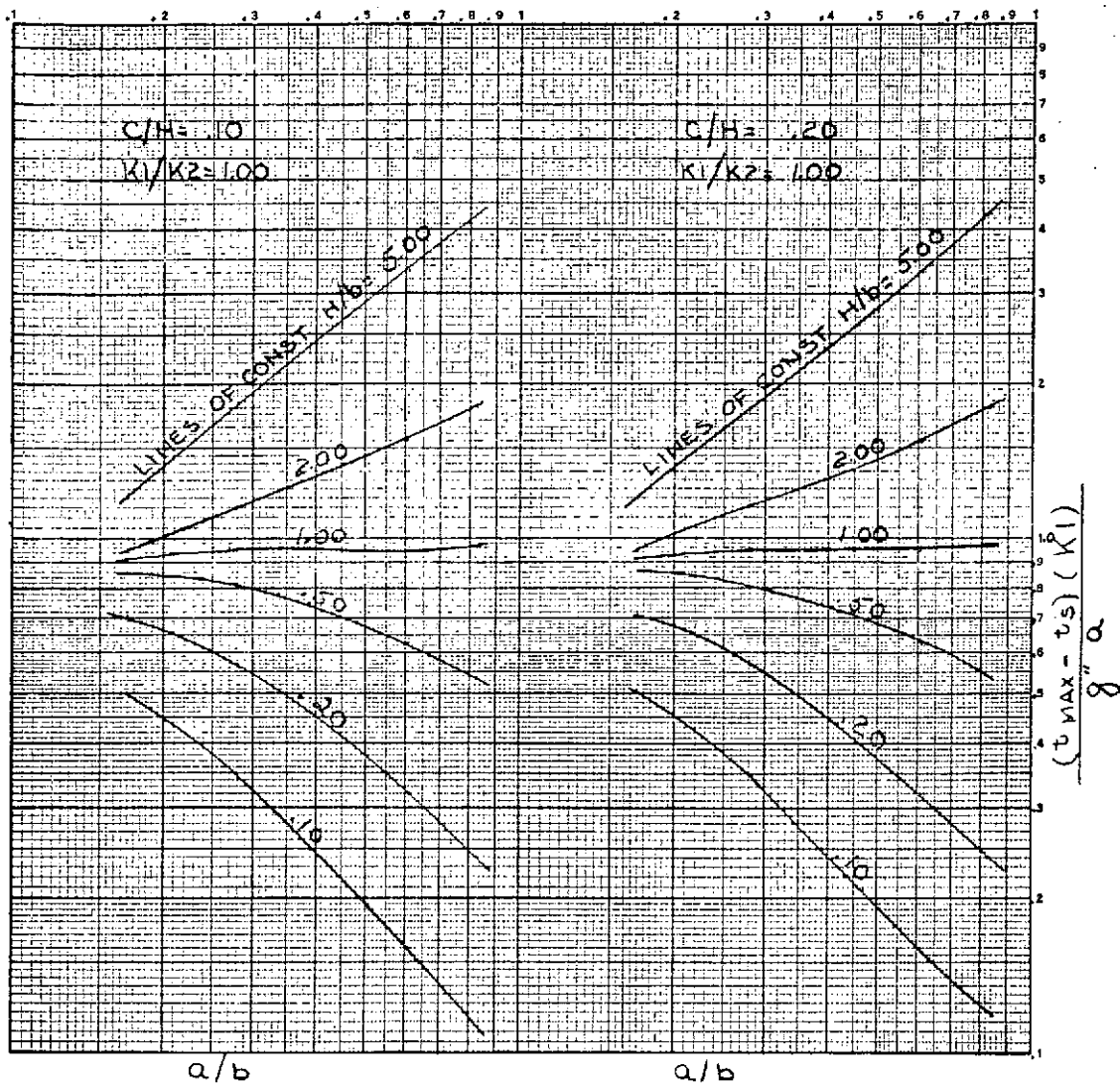


Figure 16. Sample Solution of Illustrative Problem  
(Sheet 1 of 10)

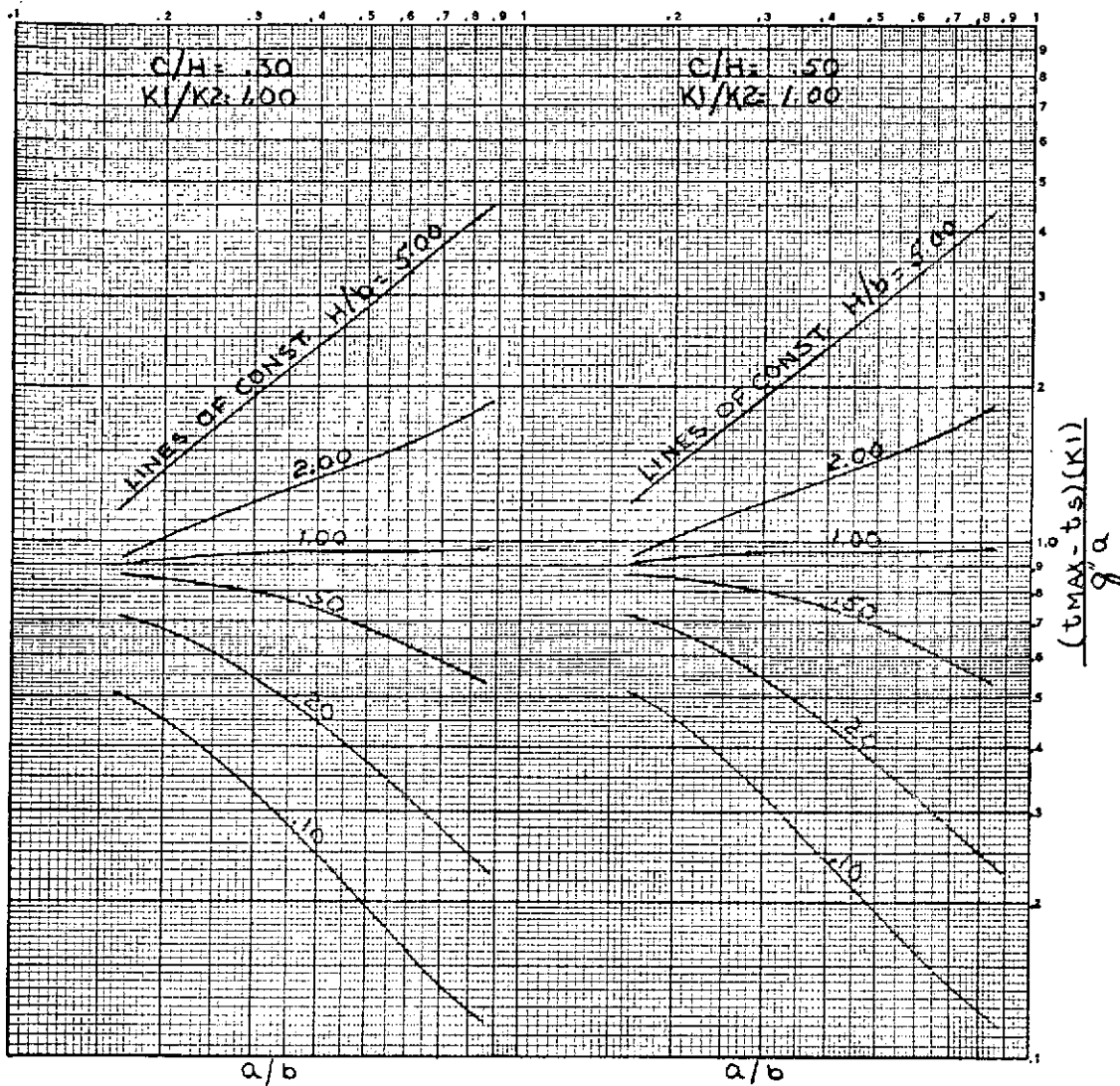


Figure 16. Sample Solution of Illustrative Problem  
(Sheet 2 of 10)



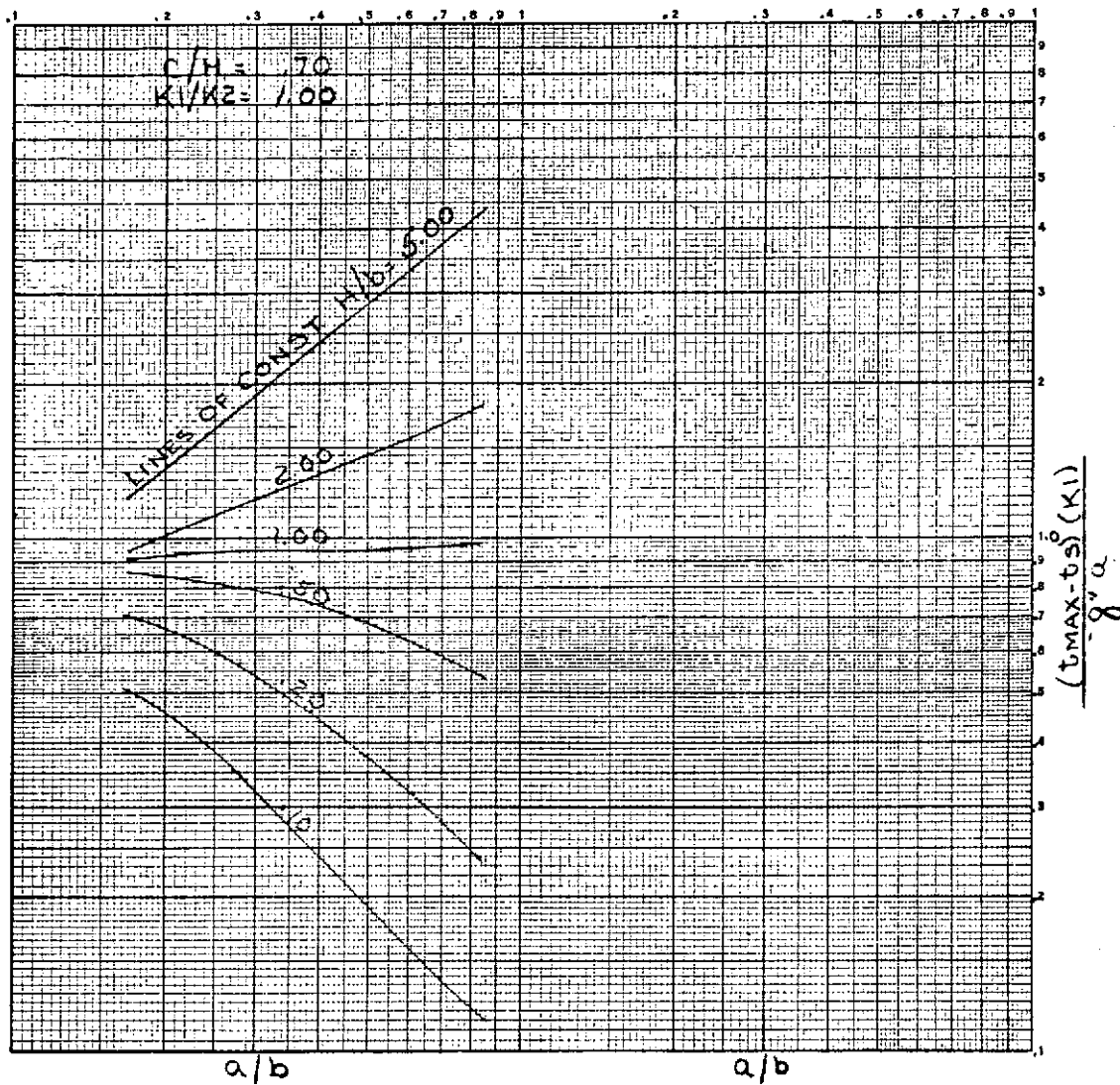


Figure 16. Sample Solution of Illustrative Problem  
(Sheet 3 of 10)

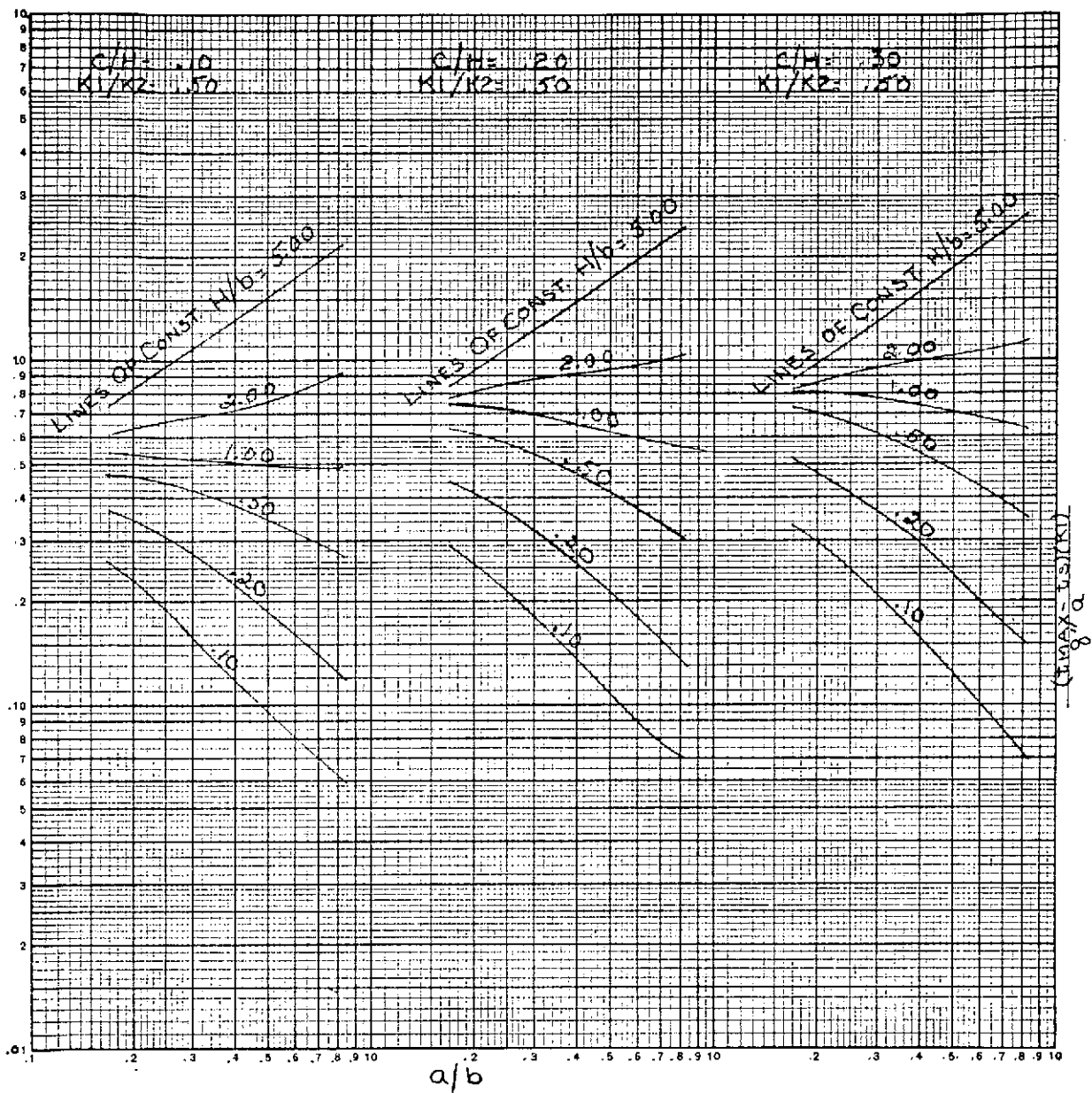


Figure 16. Sample Solution of Illustrative Problem  
(Sheet 4 of 10)

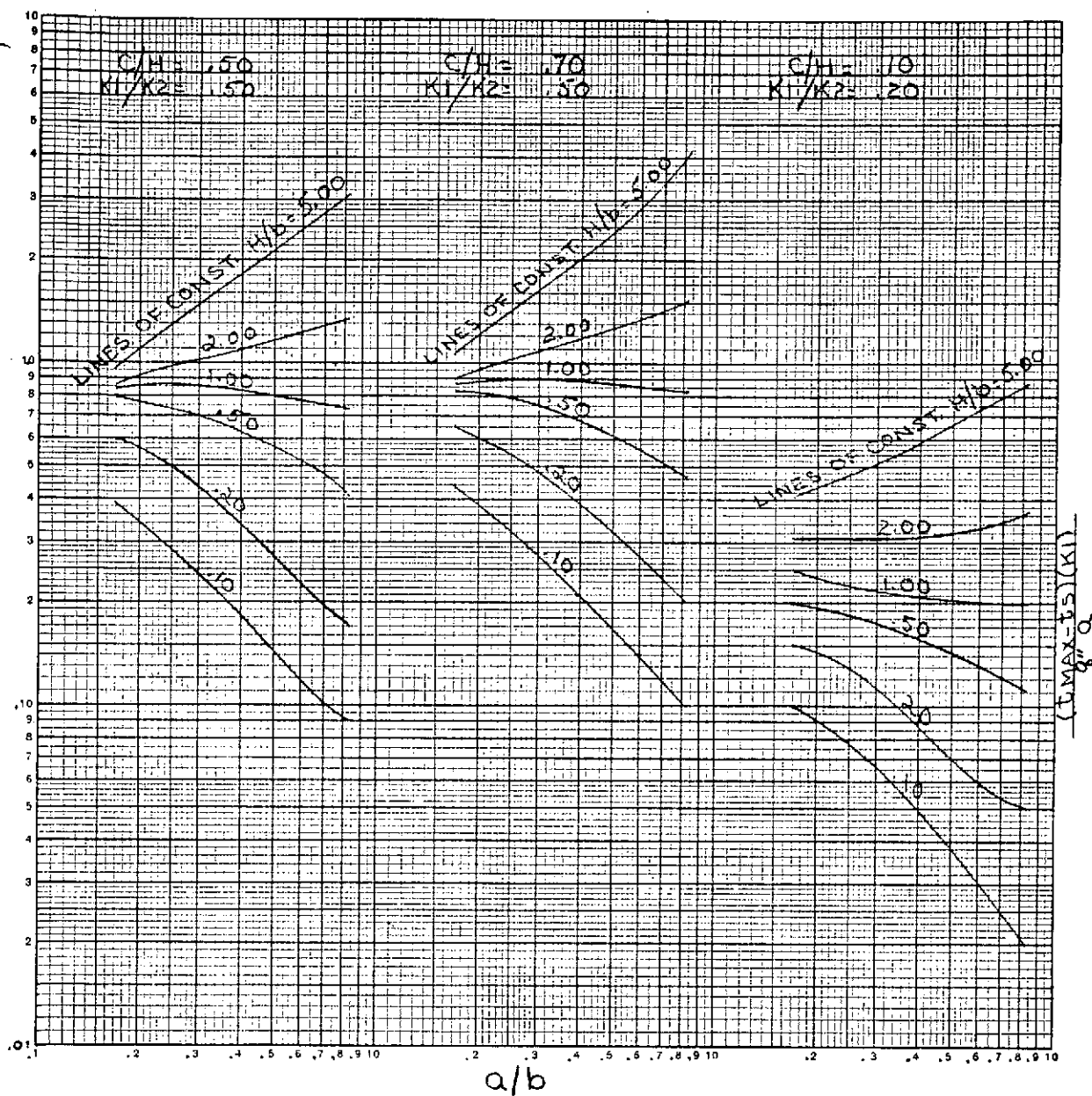


Figure 16. Sample Solution of Illustrative Problem  
(Sheet 5 of 10)

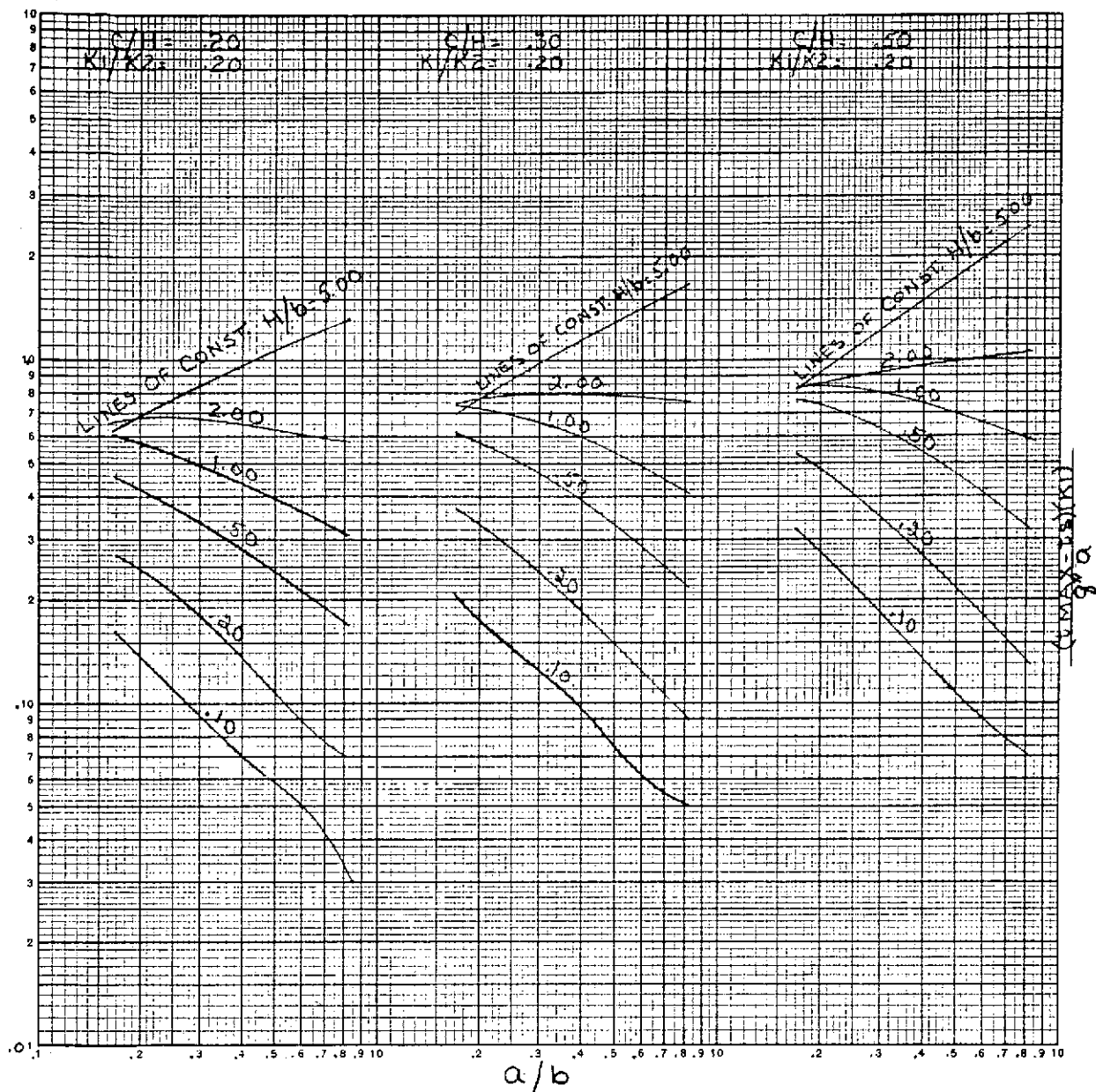


Figure 16. Sample Solution of Illustrative Problem  
(Sheet 6 of 10)

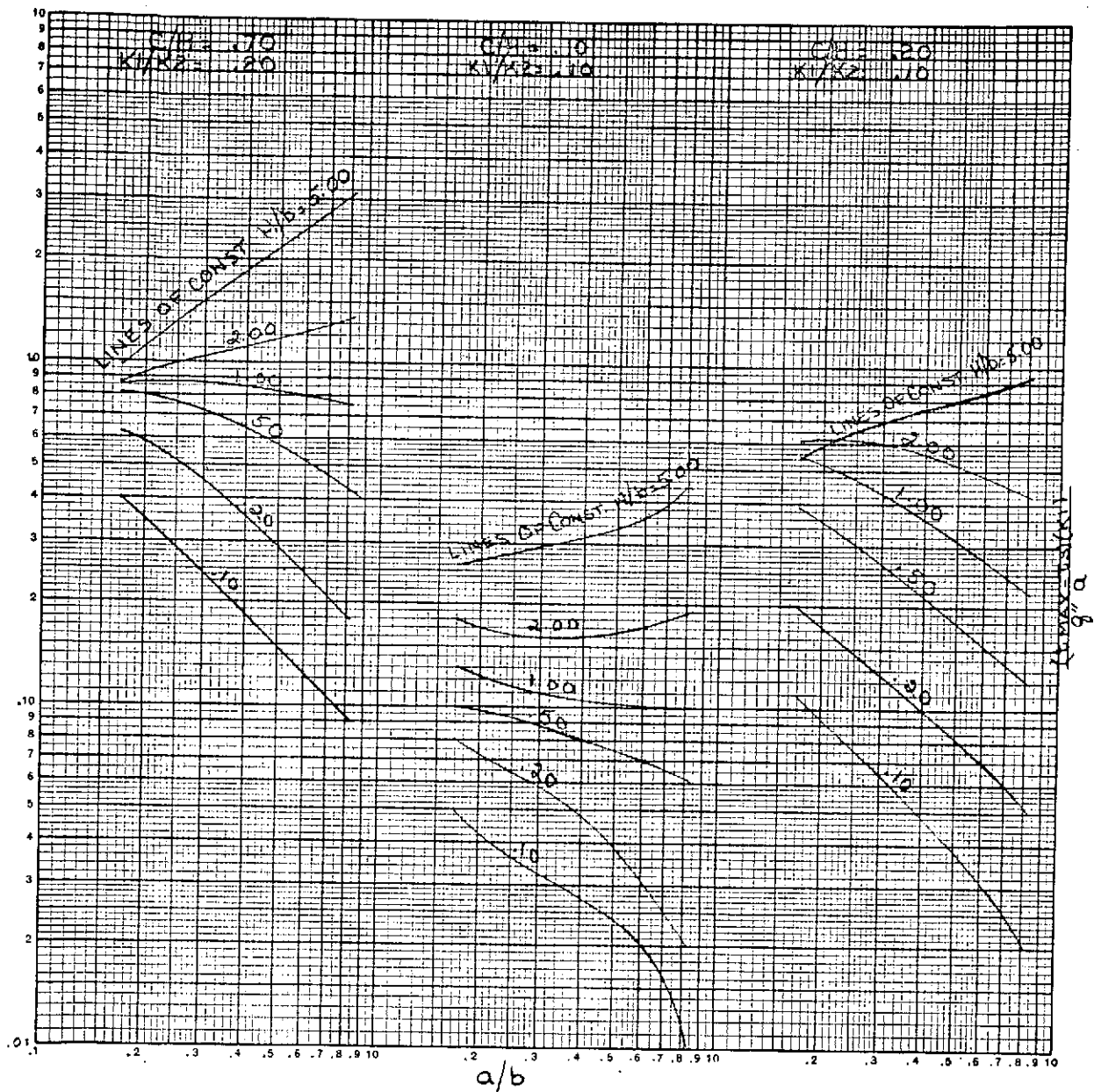


Figure 16. Sample Solution of Illustrative Problem  
(Sheet 7 of 10)

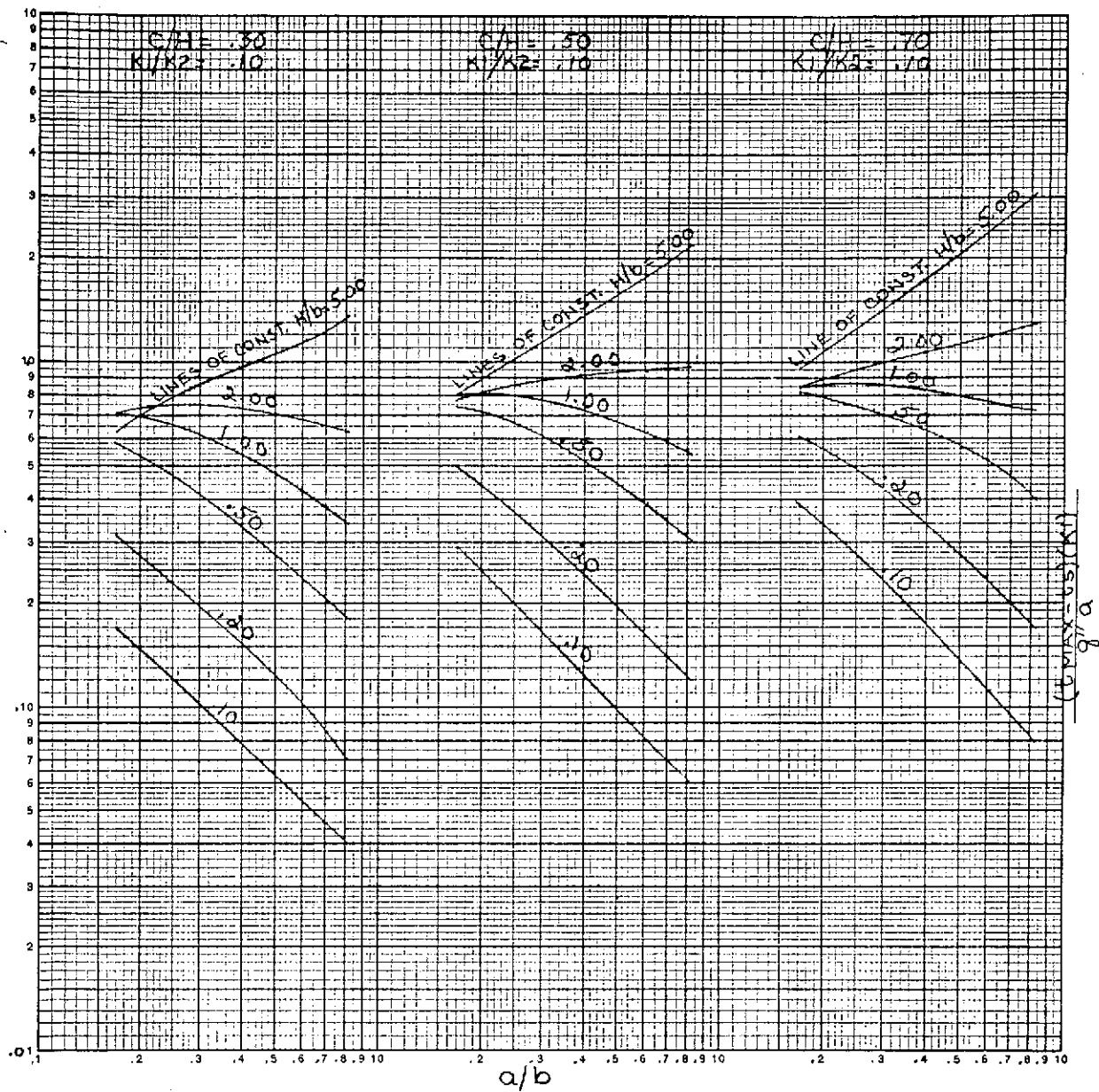


Figure 16. Sample Solution of Illustrative Problem  
(Sheet 8 of 10)

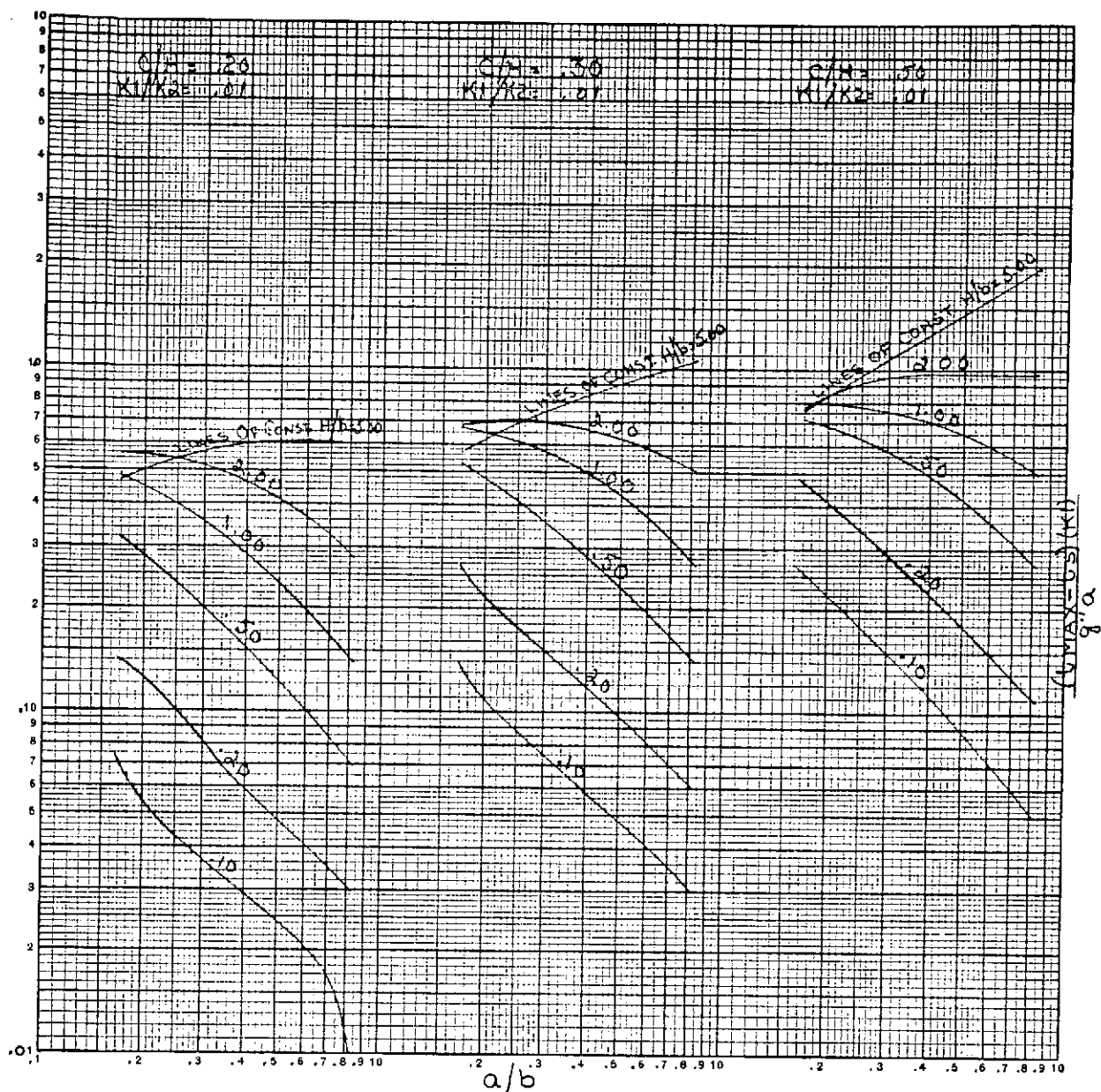


Figure 16. Sample Solution of Illustrative Problem  
(Sheet 9 of 10)

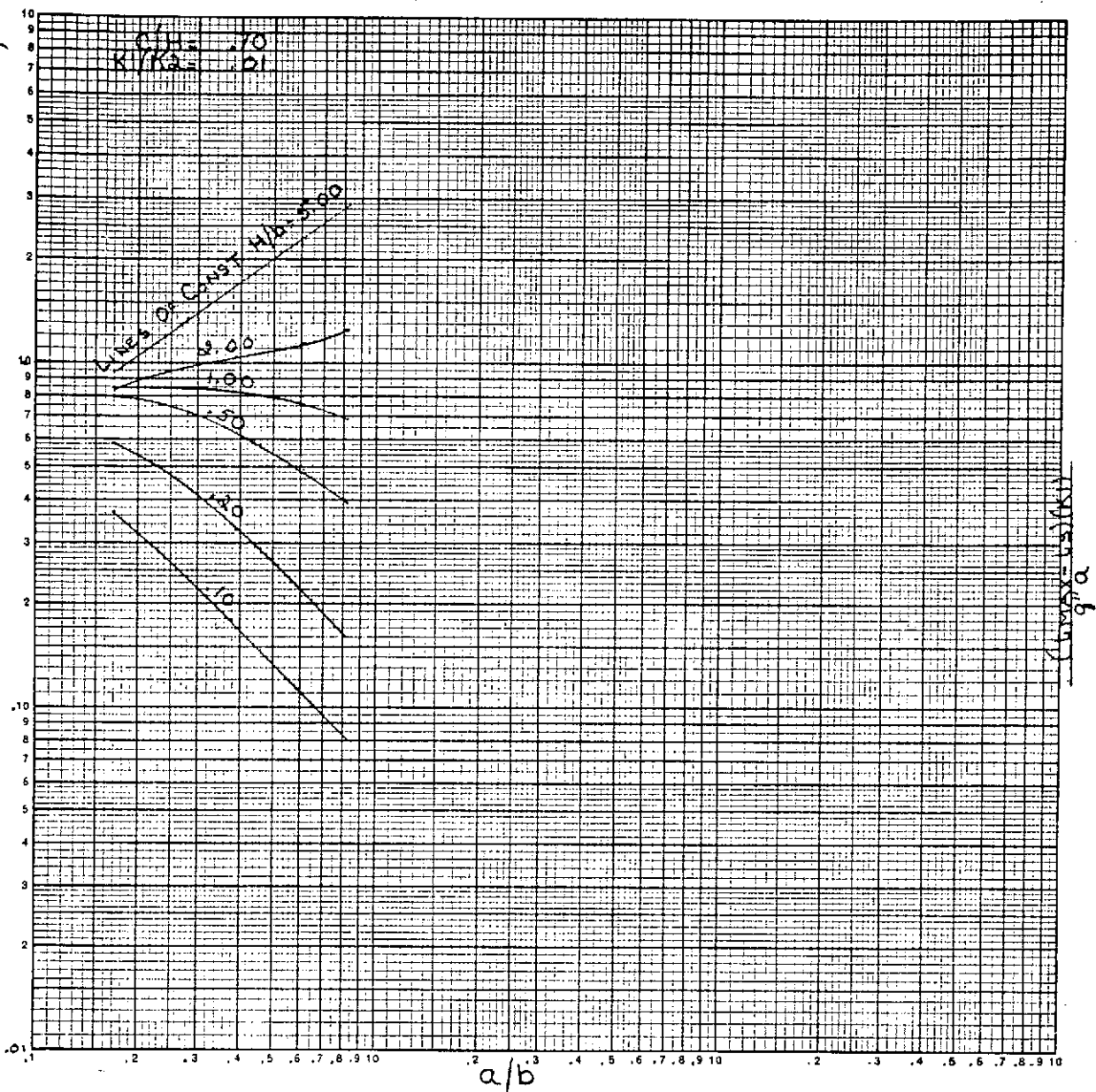


Figure 16. Sample Solution of Illustrative Problem  
(Sheet 10 of 10)



# Effect of Increasing the Number of Finite Elements on the Solution of the Illustrative Problem

An exact closed form solution exists for the cylindrical spreading resistance problem in a medium of uniform conductivity. Kennedy (Ref. 10) shows that, as  $a/b \rightarrow 0$ ,

$$\frac{(t_{\text{MAX}} - t_s) K l}{q'' a} \rightarrow 1$$

Figure 17 shows this trend for the finite difference model. With 1600 nodes,  $(t_{\text{MAX}} - t_s) K l / q''$  was calculated to be 0.9788. With 2500 nodes, the nondimensional resistance dropped to 0.9766; this reduction is attributed to the inexact treatment of the horizontal resistance of the nodes in the inner column using the equation of Jacob (Ref. 9) as described earlier.

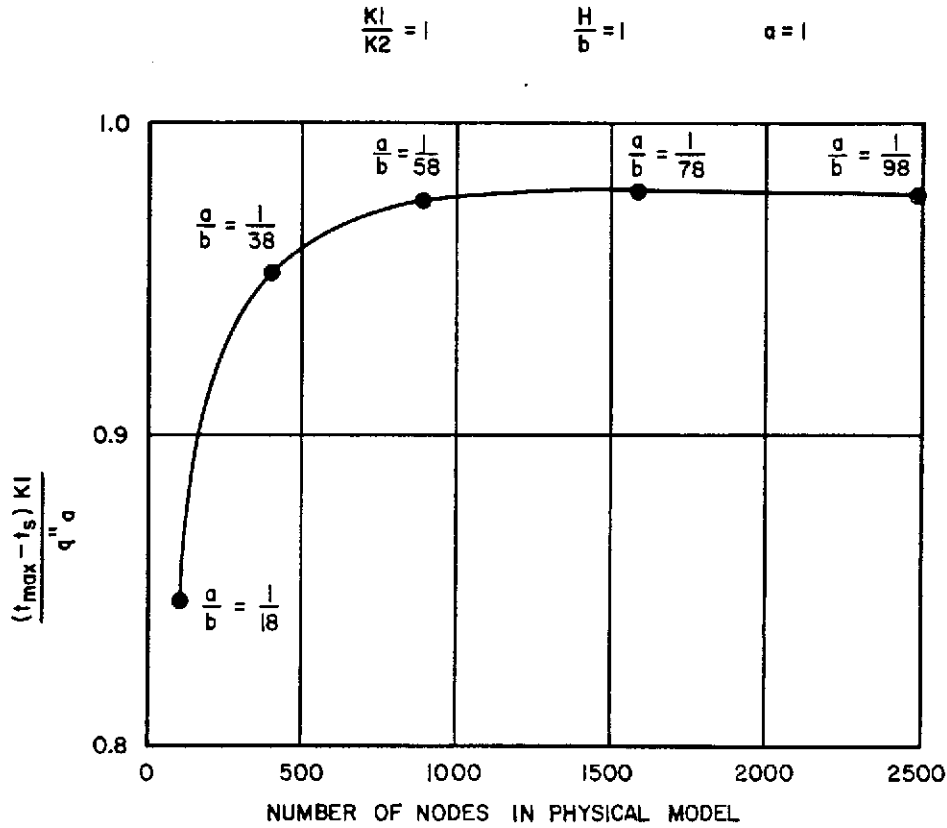


Figure 17. Maximum Nodal Temperature for Minimum  $a/b$  as a Function of Number of Nodes

It would appear that a nodal model of 900 nodes would be a near optimum number for generating solutions to this particular problem using the finite element approach.

## SECTION V

### THEORY OF SUPERPOSITION OF SOLUTIONS OF SPREADING THERMAL RESISTANCE PROBLEMS

#### A. GENERAL

The general steady state heat-conduction equation in Cartesian coordinates, known as the Poisson equation, is given by

$$\frac{\partial^2 t}{\partial x^2} + \frac{\partial^2 t}{\partial y^2} + \frac{\partial^2 t}{\partial z^2} + \frac{q'''}{K} = 0 \quad (14)$$

where

$t = t(x, y, z) =$  temperature ( $^{\circ}\text{F}$ )

$K =$  thermal conductivity (taken to be independent of temperature and position)  
(Btu/hr-ft- $^{\circ}\text{F}$ )

$q''' = q'''(x, y, z) =$  internal volumetric heat source (Btu/hr-ft $^3$ )

$x, y, z =$  Cartesian coordinates

The generalized boundary conditions vary. For example, specified temperature:

$$t(x, y, z) \Big|_{x_b, y_b, z_b} = f(x_b, y_b, z_b) \quad (15a)$$

where:

$f =$  specified function

$x_b, y_b, z_b =$  values of  $x, y, z$  on the boundary (b)

or, convection to a fluid:

$$\frac{\partial t}{\partial n} \Big|_{x_b, y_b, z_b} = \frac{h}{K} \left[ t(x, y, z) \Big|_{\text{on the boundary}} - t_f \right] \quad (15b)$$

where

$n =$  outward directed vector normal to the boundary

$h =$  Newtonian convective film coefficient (Btu/hr-ft $^2$ - $^{\circ}\text{F}$ )

$t_f =$  bulk temperature of convecting fluid ( $^{\circ}\text{F}$ )

It is convenient to rewrite equations (14), (15a), and (15b) using a temperature difference for the dependent variable that contains a reference temperature. This reference temperature is typically taken to be a specified boundary temperature, as in equation (15a), or the fluid temperature as in equation (15b).

Hence, we define this temperature difference by

$$u \triangleq t - t_{\text{reference}} \quad (16)$$

Equations (14), (15a), and (15b) can then be rewritten

$$\frac{\partial^2 u}{\partial x^2} + \frac{\partial^2 u}{\partial y^2} + \frac{\partial^2 u}{\partial z^2} + G = 0 \quad (17)$$

$$u(x, y, z) \Big|_{x_b, y_b, z_b} = g(x_b, y_b, z_b) \quad (18a)$$

$$\frac{\partial u}{\partial n} \Big|_{x_b, y_b, z_b} = \frac{h}{K} u(x_b, y_b, z_b) \quad (18b)$$

where

$$G = q'''/K$$

These equations are linear as can be seen by observing that they contain no products of the dependent variable ( $u$ ) or its derivatives. Since they are linear, any linearly independent combination of solutions will satisfy these equations due to the distributive property of linear operators, i.e.,

$$L(x_1 + x_2 + \dots) = L(x_1) + L(x_2) + \dots$$

where

$L$  is a generalized linear operator

This property may be applied to equation (17) as follows: Take  $u_1$  and  $u_2$  to be independent solutions to equation (17). Next, define

$$u_3 = a_1 u_1 + a_2 u_2$$

where  $a_1 u_1 + a_2 u_2 = 0$  if, and only if,  $a_1 = a_2 = 0$ , i.e.,  $u_1$  and  $u_2$  are linearly independent.

Now substitute  $a_1 u_1$  into equation (17), then  $a_2 u_2$  into equation (17), and add the two expressions [using (a) the shorthand operator

$$\nabla^2 = \frac{\partial^2}{\partial x^2} + \frac{\partial^2}{\partial y^2} + \frac{\partial^2}{\partial z^2}$$

and (b)  $G_1$  corresponding to the  $a_1 u_1$  solution and  $G_2$  corresponding to the  $a_2 u_2$  solution]:

$$\nabla^2 a_1 u_1 + \nabla^2 a_2 u_2 + G_1 + G_2 = 0$$

Since  $\nabla^2$  is a linear operator, and defining  $G = G_1 + G_2$ , we can write:

$$\nabla^2(a_1 u_1 + a_2 u_2) + G = 0$$

but

$$a_1 u_1 + a_2 u_2 = u_3$$

therefore,

$$\nabla^2 u_3 + G = 0$$

Thus,  $u_3$  is also a solution to equation (17). Applying the same procedure to, say, equation (18b)

$$\frac{\partial u_1}{\partial n} = \frac{h}{K} u_1$$

$$\frac{\partial u_2}{\partial n} = \frac{h}{K} u_2$$

Adding

$$\frac{\partial u_1}{\partial n} + \frac{\partial u_2}{\partial n} = \frac{h}{K} (u_1 + u_2)$$

Since  $\partial/\partial n$  is a linear operator, this can be written

$$\frac{\partial}{\partial n} (u_1 + u_2) = \frac{h}{K} (u_1 + u_2)$$

But  $u_1 + u_2 = u_3$ , then

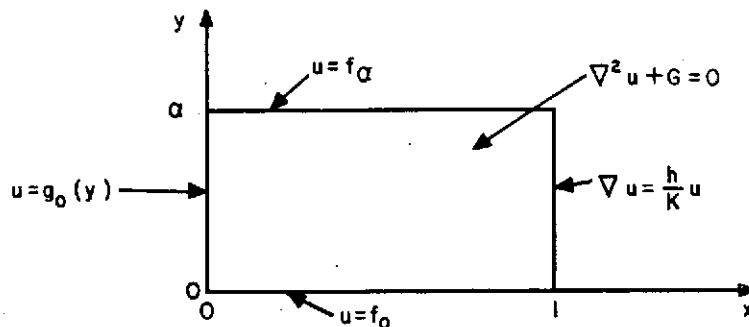
$$\frac{\partial u_3}{\partial n} = \frac{h}{K} u_3$$

Thus,  $u_3$  also satisfies the boundary condition.

## B. ADDITIVE SOLUTIONS

A useful ramification of the superposition principle lies in the fact that the solution to a complicated system may be formed by linear combinations of known solutions.

Consider a rectangular plate with internal heat generation. The governing differential equation and boundary conditions are illustrated in the following sketch:



Explicitly, we have the system

$$\begin{aligned}
 \nabla^2 u(x, y) + G(x, y) &= 0 \\
 u(x, 0) &= f_0(x) \\
 u(x, \alpha) &= f_\alpha(x) \\
 u(0, y) &= g_0(y) \\
 \nabla u(1, y) &= (h/K) u(1, y)
 \end{aligned} \tag{19}$$

The solution may now be written

$$u(x, y) = u_1(x, y) + u_2(x, y) + u_3(x, y) + u_4(x, y) \tag{20}$$

The number of ancillary problems is taken equal to the number of nonhomogeneities in the system. Since the governing equation and the first three boundary conditions are not homogeneous, the number of ancillary problems is four.

Substituting equation (20) into equation (19), we obtain the complete system:

$$\begin{aligned}
 \nabla^2 u_1 + \nabla^2 u_2 + \nabla^2 u_3 + \nabla^2 u_4 + G &= 0 \\
 u_1 + u_2 + u_3 + u_4 &= f_0 \\
 u_1 + u_2 + u_3 + u_4 &= f_\alpha \\
 u_1 + u_2 + u_3 + u_4 &= g_0 \\
 \nabla u_1 + \nabla u_2 + \nabla u_3 + \nabla u_4 &= \left(\frac{h}{K}\right) [u_1 + u_2 + u_3 + u_4] \quad \text{at } x = 1, y = y
 \end{aligned} \tag{21}$$

The set of ancillary problems corresponding to this system can now be written as:

<u>Problem 1</u>	<u>Problem 2</u>	<u>Problem 3</u>	<u>Problem 4</u>
$\nabla^2 u_1 + G = 0$	$\nabla^2 u_2 = 0$	$\nabla^2 u_3 = 0$	$\nabla^2 u_4 = 0$
$u_1 = 0$	$u_1 = 0$	$u_1 = 0$	$u_1(x, 0) = f_0(x)$
$u_2 = 0$	$u_2(x, \alpha) = f_\alpha(x)$	$u_2 = 0$	$u_2 = 0$
$u_3 = 0$	$u_3 = 0$	$u_3(0, y) = g_0(y)$	$u_3 = 0$
$\nabla u_1(1, y) = \frac{h}{K} u_1(1, y)$	$\nabla u_2(1, y) = \frac{h}{K} u_2(1, y)$	$\nabla u_3(1, y) = \frac{h}{K} u_3(1, y)$	$\nabla u_4(1, y) = \frac{h}{K} u_4(1, y)$

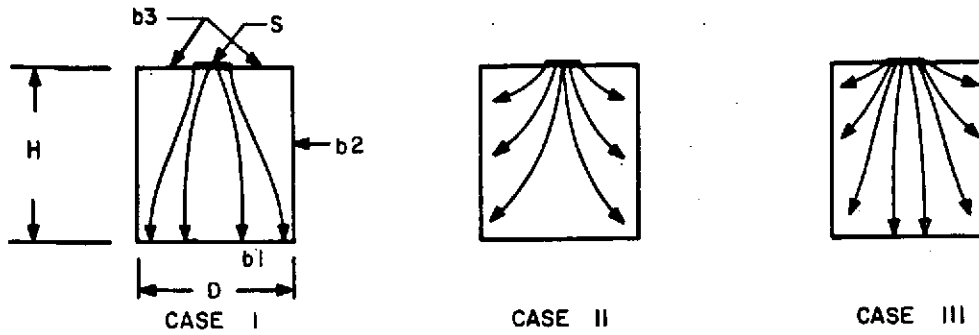
Note that each of the ancillary problems now contains only one nonhomogeneity, a much simpler form. Note also that their sum is equal to equations (21).

Hopefully, we can solve each of the ancillary problems or find the solutions in the literature. Once we have these, we merely add them to obtain the total solution to equations (19).

It was mentioned that once a system has been degenerated to a set of ancillary problems, the final solution is the sum of the individual solutions. This holds, provided the ancillary

problems are properly defined. Care must be exercised in specifying boundary conditions so that the sum of the individual solutions equals the total solution.

Consider, for example, the following three problems (taken from reference 10):



Heat, which is generated uniformly over a circular disk S, spreads by conduction through a cylinder of height H and diameter D to a constant temperature heat sink.

At first glance, the analyst might be inclined to assume that case III is the sum of cases I and II; he would be wrong. To understand why, we must correctly define the boundary conditions on each ancillary problem.

The governing differential equation in each case will be the same

$$\frac{\partial^2 u}{\partial x^2} + \frac{\partial^2 u}{\partial y^2} = 0 \quad (22)$$

The boundary conditions will be written in four parts corresponding to the regions b1, b2, b3 and S.

Case I:

$$u_I(b1) = 0$$

$$\frac{\partial u_I(b2)}{\partial n} = 0 \text{ (adiabatic surface)} \quad (23a)$$

$$\frac{\partial u_I(b3)}{\partial n} = 0$$

$$\frac{\partial u_I(S)}{\partial n} = G_I \text{ (constant flux)}$$

where n is an outward directed unit vector normal to the surface.

Case II:

$$\frac{\partial u_{II}(b1)}{\partial n} = 0$$

$$u_{II}(b2) = 0$$

$$\frac{\partial u_{II}(b3)}{\partial n} = 0$$

$$\frac{\partial u_{II}(S)}{\partial n} = G_{II}$$

(23b)

Case III:

$$u_{III}(b1) = 0$$

$$u_{III}(b2) = 0$$

$$\frac{\partial u_{III}(b3)}{\partial n} = 0$$

$$\frac{\partial u_{III}(S)}{\partial n} = G_{III}$$

(23c)

Now, add the governing differential equations for cases I and II

$$\frac{\partial^2 u_I}{\partial x^2} + \frac{\partial^2 u_I}{\partial y^2} + \frac{\partial^2 u_{II}}{\partial x^2} + \frac{\partial^2 u_{II}}{\partial y^2} = 0$$

Regrouping

$$\frac{\partial^2}{\partial x^2} (u_I + u_{II}) + \frac{\partial^2}{\partial y^2} (u_I + u_{II}) = 0$$

By our initial assumption  $u_{III} = u_I + u_{II}$ . Thus,

$$\frac{\partial^2 u_{III}}{\partial x^2} + \frac{\partial^2 u_{III}}{\partial y^2} = 0$$

The differential equation is satisfied.

Next, add boundary conditions, beginning in region b1:

$$u_I(b1) + \frac{\partial u_{II}(b1)}{\partial n} = 0$$

Note that we have mixed conditions which are inconsistent. This situation also exists in regions b2 and S (except that in region S we could define  $G_I + G_{II} \triangleq G_{III}$  to make the boundary conditions additive. Thus, case III is not the sum of cases I and II; we have, in fact, three nonanalogous systems.

### C. FURTHER EXAMPLES

An excellent set of examples of the application of superposition principles in the calculation of thermal spreading resistances may be found in Reference 1 in which the author utilizes Green's function in the calculation of thermal spreading resistances. For a discussion of Green's function see Reference 11.



## SECTION VI

### SUMMARY OF OTHER TECHNIQUES FOR CALCULATING AND ESTIMATING THERMAL SPREADING RESISTANCE

The two handiest "rules of thumb" relationships that can be used to calculate or estimate thermal spreading resistances were developed by Holm (Ref. 12) and Raillard (Ref. 13). Holm derives the equation for the thermal resistance of a circular isothermal source on the face of a semi-infinite slab as:

$$R = \frac{1}{4 a k} \quad (24)$$

where

$a$  = radius of circular source

$k$  = thermal conductivity of medium

Figure 3 (Section II) shows the temperature profiles described by Holm's equation. Figure 3 shows that 80 percent of the total resistance in a semi-infinite slab occurs within three radii of the source. It can be seen that, when the size of the source is small compared to the thickness of a slab of finite extent, Holm's equation can be used to make a conservative (high) estimate of thermal resistance. Such geometries occur often in microelectronic components.

Raillard presents similar exact solutions for circular and rectangular sources having uniform generation located on the faces of semi-infinite slabs. The equation for the thermal spreading resistance of the circular source bears a close resemblance to Holm's equation:

$$R = \frac{1}{\pi a k} \quad (25)$$

In Appendix B of his report, Raillard presents an exact closed-form solution for the rectangular source of uniform generation on a semi-infinite slab. He also derives the solution for uniform generation in a strip of infinite length and finite width on a semi-infinite slab.

Two references treat the case of the rectangular source of finite width and infinite length on a slab of finite depth. Wilcox (Ref. 14) treats the uniform heat generation source, while Gale (Ref. 15) presents thermal spreading resistances for the uniform temperature source. The results of these two studies can also be found in Reference 16.

Muller (Ref. 17) and Kennedy (Ref. 10) present exact solutions to the problem of a circular source at one end of a right cylinder with conduction to the side of the cylinder, the other end of the cylinder, or to both places. Kennedy's source is uniform while the intensity of Muller's circular heat source varies exponentially within the source region.

Hein (Ref. 1) examines steady-state heat transfer in a rectangular substrate or slab having multiple heat sources. He has integrated circuits in mind. He considers convective heat transfer and lead conduction for various heat-sinking conditions and his solutions are mathematically exact.

Finally, it might be well to point out a principle which is somewhat analogous to Saint-Venant's Principle in the theory of elasticity. Simply stated,  $T$ , the temperature in any thermal spreading resistance problem, varies with  $1/L$  where  $L$  is the distance from the source, when  $L$  is large compared with the characteristic dimension of the source. That is,

$$T \propto \frac{1}{L} \quad \text{when } L \gg a \text{ where } a \text{ is characteristic source dimension}$$

This is indicated by the form of the solution of Fourier's equation for spherical flow, i.e.,

$$q = k \frac{A dt}{dt} = \frac{k_m (t_1 - t_2)}{\int_{L_1}^{L_2} \frac{r^2 dr}{4\pi r^2}} = \frac{4\pi k_m (t_1 - t_2)}{\left(\frac{1}{L_2} - \frac{1}{L_1}\right)}$$

## SECTION VII

### PLANNED APPLICATION OF COMPUTATIONAL TECHNIQUE

General Electric's Aerospace Electronic Systems Department has developed an extremely compact and thermally efficient packaging configuration for computer circuitry. Integrated circuits are bonded to multilayered printed wiring boards which are in turn bonded to compact forced-air-cooled heat exchangers. This configuration is illustrated in Figures 18 and 19.

A heat transfer analysis program that calculates the temperature of each flatpack using Gauss-Seidel iteration is currently employed. This technique has proven costly: 200+ iterations are required. Computer costs of \$25 to \$50 per analysis have been experienced.

The exact computational technique described in this report will be implemented in the near future for this type of analysis. Costs are expected to be an order of magnitude lower than those with the iterative technique. (See Figure 9 of Section III.)

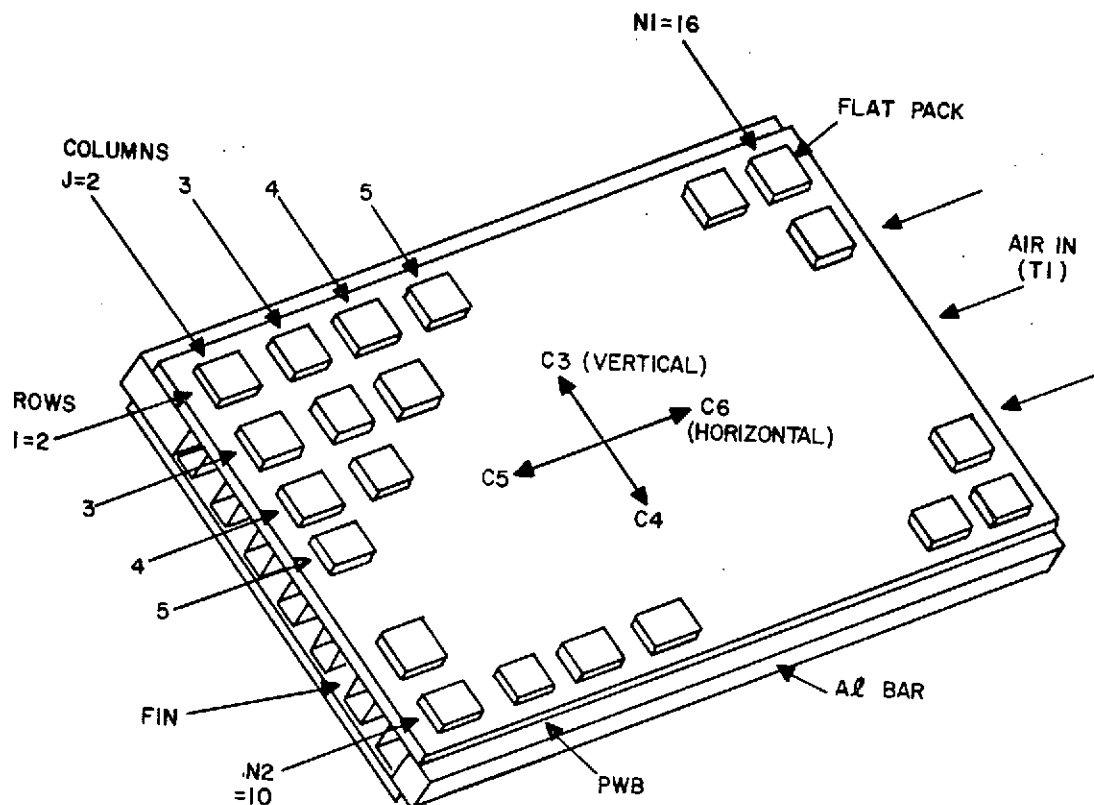


Figure 18. Memory Board Module

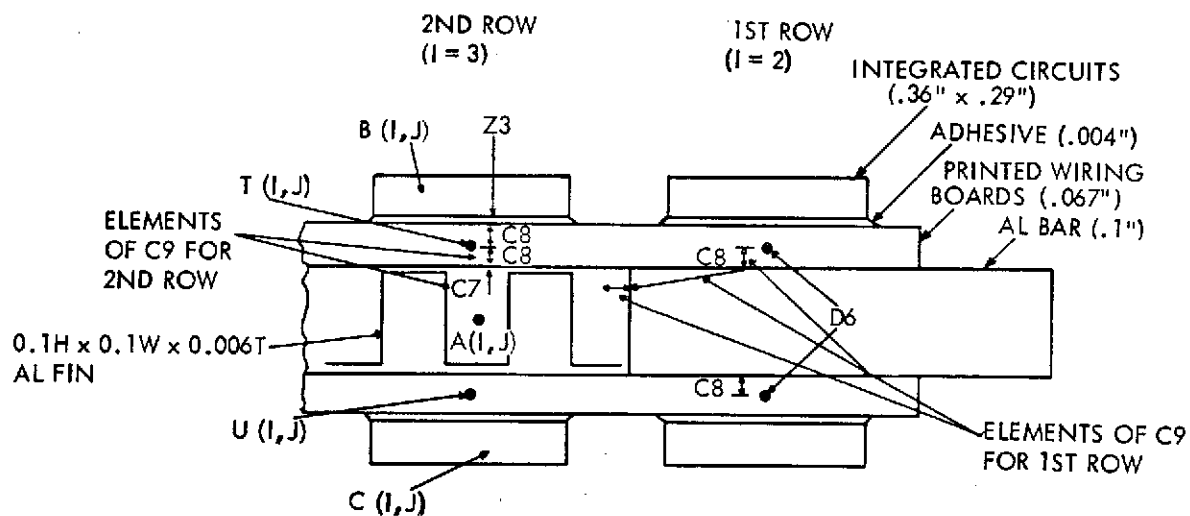


Figure 19. Location of Conductances and Temperatures

## SECTION VIII

### RECOMMENDATIONS FOR FUTURE WORK

1. The program should be rewritten for three-dimensional fields. Special attention to such techniques as using the method developed in this report for the main coefficient matrix on the submatrices themselves should be examined. The fact that very large matrices can be efficiently handled by this technique should be capitalized upon.
2. The program as it now stands should be used in a thermal spreading resistance parametric study similar to but larger in scope than the illustrative problem of this study. Nine hundred to sixteen hundred finite elements should be used in such data generation.

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16. References 15 and 16 may be found in General Electric Heat Transfer Design Data Book, Section G502-4, p. 15, January 1968 (this book is both in print and in open literature).
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## APPENDIX

### GENERAL FORTRAN Y VERSION OF COMPUTER PROGRAM



```

$ IDENT 727-9C4,KELLY NED ,DEL-B 65078300044700
$ OPTION FORTRAN
$ USE MEMORY/1000/
$ ENTRY MAIN
$ FORTY
$ INCODE IBMF
CMAIN MAIN
SUBROUTINE MAIN
PARAMETER MAXCOR=1000
COMMON /MEMORY/CORE(MAXCOR)
COMMON /FILES/INFILE,IOFILE,IFILE1,IFILE2
COMMON /TIMES/ITIME(2),IDATE(2),DELTIM
COMMON /DEBUG/IDEBUG
PARAMETER MAXMAT=69
PARAMETER MAXOFF=6
DIMENSION IOFF(MAXOFF)
DIMENSION KARD(14)
PARAMETER MAXTIT=12
DIMENSION ITITLE(MAXTIT)
PARAMETER MAXTIM=2
DATA KDEBUG/5HDEBUG/
DATA IDEBUG/1/
DATA INFILE/05/
DATA IOFILE/06/
DATA IFILE1/07/
DATA JFILE1/6H000007/
DATA IFILE2/08/
DATA ISIZE/4HSIZE/
DATA ICORE/MAXCOR/
DATA KTITLE/6HTITLE /
CALL FXOPT(67,1,1,0)
CALL FXOPT(68,0,0,0)
CALL FXOPT(69,0,0,0)
CALL FXOPT(70,0,0,0)
CALL FXOPT(71,0,0,0)
READ(INFILE,77)KARD
IF(KARD(1).NE.KTITLE) GO TO 94
CALL SUPERT(MAXTIT,KARD(2))
94 CONTINUE
CALL NEWLIN
WRITE(IOFILE,78)KARD
CALL TIMDAT(ITIME,IDATE)
CALL ELTIME(DELTIM)

```

```

558 CONTINUE
  READ(INFILE,77)KARD
77  FORMAT(13A6,A2)
  CALL NEWLIN
  WRITE(IOFILE,78)KARD
78  FORMAT(2H *,13A6,A2,1H*)
  IF(KARD(1).NE.KDEBUG) GO TO 557
  IDEBUG=0
  GO TO 558

557 CONTINUE
  DECODE(KARD,1)KEY,N
  1  FORMAT(A6,4X,I5)
  IF(KEY.EQ.ISIZE) GO TO 2
  CALL NEWLIN
  WRITE(IOFILE,55)
55  FORMAT(40H THE ABOVE CARD SHOULD BE A 'SIZE' CARD.)
  STOP
  2  IF(N.LT.MAXMAT) GO TO 222
  CALL NEWLIN
  WRITE(IOFILE,223)MAXMAT
223  FORMAT(18H SIZE GREATER THAN,I10)
  STOP
222  IF(N.GT.0) GO TO 224
  CALL NEWLIN
  WRITE(IOFILE,225)
225  FORMAT(17H SIZE LESS THAN 1)
  STOP
224  NSQ=N*N
  CALL SETNUM(2*N*3)
C    RECORDS ARE IN SYSTEM STANDARD RANDOM FORMAT
C    WHICH MEANS THAT IF A RECORD IS GREATER THAN 318 WORDS
C          THEN THE RECORD WILL BEGIN IN A NEW BLOCK
C          AND END A BLOCK EVERY TIME
C
C    I TRIED USING PURE DATA RANDOM FILES(11-13-72), BUT
C    FOR SOME REASON THEY DID NOT SEEM TO WORK PROPERLY.
  NBLOCK=((NSQ-1)/318 + 1)*(2*N + 3)
  CALL NEWLIN
  WRITE(IOFILE,87)NBLOCK
87  FORMAT(110,43H BLOCKS OF RANDOM DISC STORAGE ARE REQUIRED)
  NLINKS=(NBLOCK-1)/12 + 2
  CALL NEWLIN
  WRITE(IOFILE,86)NLINKS

```

```

86 FORMAT(110,42H LINKS OF RANDOM DISC STORAGE ARE REQUIRED)
   NTIMES=0
81 CALL GETMOR(1,IERR,NLINKS,JFILE1)
   IF(IERR.EQ.0) GO TO 88
C   REQUEST WAS REFUSED
   CALL NEWLIN
   WRITE(IOFILE,82)
82 FORMAT(29H REQUEST FOR DISC WAS REFUSED)
   NTIMES=NTIMES+1
   IF(NTIMES.LT.MAXTIM) GO TO 81
   CALL NEWLIN
   WRITE(IOFILE,83) NTIMES
83 FORMAT(25H REQUEST FOR DISC REFUSED,18,16H TIMES, GIVE UP,)
   STOP
88 CALL SETSIZ(NSQ)
C   SEE IF WE HAVE ENOUGH CORE
   MCORE=5*NSQ + N
   CALL NEWLIN
   WRITE(IOFILE,101)ICORE
101 FORMAT(110,38H WORDS OF CORE ARE CURRENTLY AVAILABLE)
   CALL NEWLIN
   WRITE(IOFILE,102)MCORE
102 FORMAT(110,39H WORDS OF CORE ARE REQUIRED FOR THE JOB)
   IF(MCORE.LE.ICORE) GO TO 3
C   GET MORE CORE
C   ICORE IS AUTOMATICALLY UPDATED TO REFLECT THE ACTUAL NUMBER
C   OF WORDS THERE ARE UPON RETURN
C   THE ROUTINE DOES NOT FAIL
C   IT KEEPS TRYING UNTIL IT GETS THE CORE IT WANTS
   CALL NEWLIN
   WRITE(IOFILE,103)
103 FORMAT(33H GET THE ADDITIONAL CORE REQUIRED)
   CALL GIMME(MCORE,ICORE,CORE)
C   COMPUTE LINEAR OFFSET FOR EACH MATRIX
3   IOFF(1)=1
   DO 4 I=2,MAXOFF
4   IOFF(I)=IOFF(I-1)+NSQ
   NUM=N
C   RESERVE SPACE FOR 2*N MATRICES
   J=2*NUM
   DO 91 I=1,J
91 CALL NEWNUM(K)
   CALL FIRST(NUM,CORE(IOFF(1)),NUM,NUM,CORE(IOFF(2)),NUM,NUM,

```

```

1      CORE(IOFF(3)),NUM,NUM,CORE(IOFF(4)),NUM,NUM,
1      CORE(ICFF(5)),NUM,NUM,CORE(IOFF(6)),NUM)

```

```

CALL FINISH

```

```

STOP

```

```

END

```

```

CPFIRST      FIRST

```

```

SUBROUTINE FIRST(NUM,Q1,NR1,NC1,Q2,NR2,NC2,Q3,NR3,NC3,Q4,NR4,NC4,
1      Q5,NR5,NC5,IVEC,NVEC)

```

```

COMMON /FILES/INFILE,IOFILE,IFILE1,IFILE2

```

```

COMMON /DEBUG/DEBUG

```

```

DIMENSION IVEC(NVEC)

```

```

REAL Q1(NR1,NC1)

```

```

REAL Q2(NR2,NC2)

```

```

REAL Q3(NR3,NC3)

```

```

REAL Q4(NR4,NC4)

```

```

REAL Q5(NR5,NC5)

```

```

DIMENSION IQ1(4)

```

```

DIMENSION IQ2(4)

```

```

DIMENSION IQ3(4)

```

```

DIMENSION IQ4(4)

```

```

DIMENSION IQ5(4)

```

```

IQ1(1)=0

```

```

IQ2(1)=0

```

```

IQ3(1)=0

```

```

IQ4(1)=0

```

```

IQ5(1)=0

```

```

IQ1(2)=0

```

```

IQ2(2)=0

```

```

IQ3(2)=0

```

```

IQ4(2)=0

```

```

IQ5(2)=0

```

```

IQ1(3)=NR1

```

```

IQ2(3)=NR2

```

```

IQ3(3)=NR3

```

```

IQ4(3)=NR4

```

```

IQ5(3)=NR5

```

```

IQ1(4)=NC1

```

```

IQ2(4)=NC2

```

```

IQ3(4)=NC3

```

```

IQ4(4)=NC4

```

```

IQ5(4)=NC5

```

```

CALL SETUPA(Q1,NR1,NC1,Q2,NR2,NC2,Q3,NR3,NC3,Q4,NR4,NC4,
1      Q5,NR5,NC5,IVEC,NVEC,NUM)

```

C  
C  
C  
GENERATE RECURSION COEFFICIENTS A' AND B'

CALL RSTR(Q1,IQ1,1)  
CALL RSTR(Q2,IQ2,2)  
CALL RSTR(Q3,IQ3,3)  
DO 10 NAME=3,(NUM\*2-1),2  
CALL MPPY(Q3,IQ3,Q2,IQ2,Q4,IQ4,IERR)  
CALL MATIDN(Q5,IQ5,NUM)  
CALL MSUB(Q5,IQ5,Q4,IQ4,Q4,IQ4,IERR)  
CALL MINV(Q4,NUM,NUM,IVEC,DET)  
CALL RSTR(Q5,IQ5,NAME+1)  
CALL MPPY(Q4,IQ4,Q5,IQ5,Q2,IQ2,IERR)  
CALL SAVE(Q2,IQ2,NAME+1)  
CALL MPPY(Q3,IQ3,Q1,IQ1,Q5,IQ5,IERR)  
CALL MPPY(Q4,IQ4,Q5,IQ5,Q1,IQ1,IERR)  
CALL SAVE(Q1,IQ1,NAME)

10 CONTINUE

IF(IDEBUG.NE.0) GO TO 666  
CALL NEWLIN  
WRITE(IOFILE,566)

566 FORMAT(14H DEBUG POINT C)  
CALL MATMAT

666 CONTINUE

C  
C  
C  
USE A' AND B' TO SOLVE FOR UNKNOWNNS

CALL MATZER(Q1,IQ1)  
Q1=X  
CALL RSTR(Q2,IQ2,NUM\*2-1)  
CALL MATZER(Q2,IQ2)  
CALL SAVE(Q2,IQ2,NUM\*2-1)  
Q2=T

NAME=NUM\*2

20 NAME=NAME-2

CALL RSTR(Q3,IQ3,NAME)

Q3= S,Q,0,...

CALL MPPY(Q3,IQ3,Q2,IQ2,Q1,IQ1,IERR)  
IF(IERR.NE.0) CALL QUIT(IERR)

Q1= X

CALL RSTR(Q2,IQ2,NAME-1)

Q2= R,P,N,...

CALL MADD(Q1,IQ1,Q2,IQ2,Q2,IQ2,IERR)

```

      IF(IERR.NE.0) CALL QUIT(IERR)
      CALL SAVE(Q2,IQ2,NAME=1)
C      Q2= R,P,N,...
      IF(NAME.GE.4) GO TO 20
      IF(IDEBUG.NE.0) GO TO 667
      CALL NEWLIN
      WRITE(IOFILE,567)
567  FORMAT(14H DEBUG POINT:D)
      CALL MATMAT
      667 CONTINUE
C
C
C      PRINT OUT THE RESULTS
      CALL NEWPAG
      CALL NEWLIN
      WRITE(IOFILE,8801)
8801  FORMAT(9H A MATRIX)
      CALL RSTR(Q1,IQ1,1)
      CALL PMAT(Q1,IQ1(1),IQ1(2),IQ1(3),IQ1(4))
      CALL NEWPAG
      CALL NEWLIN
      WRITE(IOFILE,8802)
8802  FORMAT(9H C MATRIX)
      CALL RSTR(Q1,IQ1,3)
      CALL PMAT(Q1,IQ1(1),IQ1(2),IQ1(3),IQ1(4))
      CALL NEWPAG
      CALL NEWLIN
      WRITE(IOFILE,8803)
8803  FORMAT(9H P MATRIX)
      CALL RSTR(Q1,IQ1,(NUM-2)*2-1)
      CALL PMAT(Q1,IQ1(1),IQ1(2),IQ1(3),IQ1(4))
      CALL NEWPAG
      CALL NEWLIN
      WRITE(IOFILE,8804)
8804  FORMAT(9H R MATRIX)
      CALL RSTR(Q1,IQ1,(NUM-1)*2-1)
      CALL PMAT(Q1,IQ1(1),IQ1(2),IQ1(3),IQ1(4))
      CALL NEWPAG
      CALL NEWLIN
      WRITE(IOFILE,8805)
8805  FORMAT(9H T MATRIX)
      CALL RSTR(Q1,IQ1,(NUM )*2-1)
      CALL PMAT(Q1,IQ1(1),IQ1(2),IQ1(3),IQ1(4))

```

```

C      RETURN
      END FIRST
      END
CSETUPA      SETUPA
      SUBROUTINE SETUPA(M,NRH,NCH,V,NRV,NCV,C,NRC,NCC,X,NRX,NCX,
1             Y,NRY,NCY,IVEC,NVEC,NUM)
      COMMON /FILES/INFILE,IOFILE,IFILE1,IFILE2
      COMMON /DEBUG/IDBUG
      DIMENSION IVEC(NVEC)
      DIMENSION H(NRH,NCH)
      DIMENSION V(NRV,NCV)
      DIMENSION C(NRC,NCC)
      DIMENSION X(NRX,NCX)
      DIMENSION Y(NRY,NCY)
      DIMENSION IH(4)
      DIMENSION IV(4)
      DIMENSION IC(4)
      DIMENSION IX(4)
      DIMENSION IY(4)
      DIMENSION KARD(14)
      DATA IHEAT/4*HHEAT/
      IH(1)=NUM
      IH(2)=NUM
      IH(3)=NRH
      IH(4)=NCH
      IV(1)=NUM
      IV(2)=NUM
      IV(3)=NRV
      IV(4)=NCV
      IC(1)=NUM
      IC(2)=1
      IC(3)=NRC
      IC(4)=NCC
      IX(1)=NUM
      IX(2)=NUM
      IX(3)=NRX
      IX(4)=NCX
      IY(1)=NUM
      IY(2)=NUM
      IY(3)=NRY
      IY(4)=NCY
      CALL NEWNUM(INDEXC)
      CALL NEWNUM(INDEXH)

```

```

CALL NEWNUM(INDEXV)
CALL MATZER(H,IH)
CALL MATZER(V,IV)
CALL MATZER(C,IC)
PI=3.14159265
C1=.5/PI
R1=C1*(ALOG(2.0))/(2.0*PI)
R2=R1/2.0
H(1,1)=1.0/R1
H(NUM,1)=1.0/R1
DO 180 M=2,NUM-1
180 H(M,1)=2.0*H(1,1)
DO 210 M=1,NUM
210 V(M,1)=PI/2.0
DO 310 M=1,NUM
DO 300 N=2,NUM
H(M,N)=1.0/(1.0/(4.0*PI)*ALOG(FLOAT(N)/(FLOAT(N)-1.0)))
V(M,N)=PI*4.0*(FLOAT(N)-1.0)
IF(M.GT.1) GO TO 280
H(1,N)=.5*H(1,N)
280 H(NUM,N)=.5*H(NUM,N)
V(M,10)=PI*(4.0*FLOAT(N)-5.0)/2.0
300 CONTINUE
310 CONTINUE
DO 340 M=1,NUM
340 H(M,NUM)=0.0
DO 370 N=1,NUM
370 V(1,N)=0.0
C2=1.0
C3=1.0
DO 460 M=1,NUM
DO 450 N=1,NUM
V(M,N)=C3*V(M,N)
H(M,N)=C2*H(M,N)
450 CONTINUE
460 CONTINUE
READ(INFILE,461,END=468)KARD
461 FORMAT(13A6,A2)
CALL NEWLIN
WRITE(IOFILE,464)KARD
464 FORMAT(2H *,13A6,A2,1H*)
IF(KARD(1).EQ.IHEAT) GO TO 462
CALL NEWLIN

```



```

WRITE(IOFILE,463)
463 FORMAT(35H ABOVE CARD SHOULD BE A 'HEAT' CARD)
STOP
462 DECODE(KARD,465)I1,I2
465 FORMAT(10X,2I5)
IF(I1.LE.0.OR.I1.GT.I2 ) GO TO 472
IF(I2.GT.NUM) GO TO 473
GO TO 479
472 CALL NEWLIN
WRITE(IOFILE,474)
474 FORMAT(20H I1 IS OUT OF BOUNDS)
STOP
473 CALL NEWLIN
WRITE(IOFILE,475)
475 FORMAT(20H I2 IS OUT OF BOUNDS)
STOP
479 CONTINUE
DO 466 N=1,NUM
466 C(N,1)=0.0
DO 467 N=1,I2
467 C(N,1)=V(2,N)*2.0
CALL NEWPAG
CALL NEWLIN
WRITE(IOFILE,469)
469 FORMAT(26H INITIAL HEAT INPUT MATRIX)
CALL PMAT(C,IC(1),IC(2),IC(3),IC(4))
GO TO 471
468 CALL NEWLIN
470 FORMAT(49H UNEXPECTED END OF FILE. EXPECTING A 'HEAT' CARD)
WRITE(IOFILE,470)
STOP
471 CONTINUE
CALL NEWPAG
CALL NEWLIN
WRITE(IOFILE,701)
701 FORMAT(9H H MATRIX)
CALL PMAT(H,IH(1),IH(2),IH(3),IH(4))
CALL NEWPAG
CALL NEWLIN
WRITE(IOFILE,702)
702 FORMAT(9H V MATRIX)
CALL PMAT(V,IV(1),IV(2),IV(3),IV(4))
CALL SAVE(C,IC,INDEXC)

```

```

CALL SAVE(H,IH,INDEXH)
CALL SAVE(V,IV,INDEXV)
IF(IDEBUG.NE.0) GO TO 664
CALL NEWLIN
WRITE(IOFILE,564)
564 FORMAT(14H DEBU9 POINT A)
CALL MATHAT
664 CONTINUE
C
C THE MATRICES ON THE DIAGONAL (AND OF COURSE THEIR INVERSES)
C ARE DIFFERENT ONLY FOR THE FIRST, SECOND, AND LAST TIMES.
DO 1150 M=1,NUM
  I00=1
  IF(M.EQ.1.OR.M.EQ.2.OR.M.EQ.NUM) I00=0
  IX(1)=NUM
  IX(2)=NUM
  CALL MATZER(X,IX)
  IY(1)=NUM
  IY(2)=NUM
  CALL MATZER(Y,IY)
  IF(I00.EQ.0) IC(1)=NUM
  IF(I00.EQ.0) IC(2)=NUM
  IF(I00.EQ.0) CALL MATZER(C,IC)
  CALL RSTR(H,IH,INDEXH)
  DO 720 N=1,NUM
    IF(N.EQ.1.OR.N.EQ.NUM) GO TO 590
    IF(I00.EQ.0) C(N,N-1)=0.0
    IF(I00.EQ.0) C(N,N+1)=0.0
590 IF(N.LT.2) GO TO 610
    IF(I00.EQ.0) C(N,N-1)=-H(M,N-1)
610 IF(N.GE.NUM) GO TO 630
    IF(I00.EQ.0) C(N,N+1)=-H(M,N)
630 IF(M.GE.NUM) GO TO 640
    X(N,N)=-V(M+1,N)
640 Y(N,N)=-V(M,N)
    C33=0.0
    IF(N.EQ.1) GO TO 680
    C33=C(N,N-1)
680 IF(N.GE.NUM) GO TO 700
    C33=C33+C(N,N+1)
700 IF(I00.EQ.0) C(N,N)=-C33+X(N,N)+Y(N,N)
720 CONTINUE
    IF(I00.EQ.0) CALL MINV(C,NUM,NUM,IVEC,DET)

```

```

CALL MPPY(C,IC,X,IX,H,IH,IERR)
IF(IERR.NE.0) CALL QUIT(IERR)
CALL MNEG(H,IH)
C   SAVE H (B,D,F,...)
    CALL SAVE(H,IH,M*2)
    IF(M.GT.1) GO TO 888
    CALL RSTR(H,IH,INDEXC)
    CALL MPPY(C,IC,H,IH,X,IX,IERR)
    IF(IERR.GT.0) CALL QUIT(IERR)
C   SAVE A
    CALL SAVE(X,IX,M*2-1)
    GO TO 1150
888 CALL MPPY(C,IC,Y,IY,X,IX,IERR)
    CALL MNEG(X,IX)
    IF(IERR.NE.0) CALL QUIT(IERR)
C   SAVE (C,E,G,...)
    CALL SAVE(X,IX,M*2-1)
1150 CONTINUE
    IF(IDEBUG.NE.0) GO TO 665
    CALL NEWLIN
    WRITE(IOFILE,565)
565 FORMAT(14H DEBUG POINT 8)
    CALL MATMAT
665 CONTINUE
    RETURN
C   END SETUPA
    END

CSAVE      SAVE
SUBROUTINE SAVE(A,IA,INDEX)
COMMON /FILES/INFILE,IOFILE,IFILE1,IFILE2
DIMENSION A(1)
DIMENSION IA(4)
DIMENSION IB(3)
DATA NRW/0/
DATA KOUNT/0/
IF(INDEX.LT.1.OR.INDEX.GT.KOUNT) GO TO 801
IF(IA(1).LE.0) CALL QUIT(1)
IF(IA(2).LE.0) CALL QUIT(1)
C   CHECK TO SEE IF RANDOM RECORD SIZE IS LARGE ENOUGH
    IF((IA(1)+IA(2)).GT.MAXWRD) CALL QUIT(1)
    IB(1)=IA(1)
    IB(2)=IA(2)
    IB(3)=1

```

```

WRITE(IFILE2',INDEX)IB
NR=IA(1)
NC=IA(2)
NCOLS=IA(4)
I2=NR-1
I3=NCOLS*(NR-1)+1
WRITE(IFILE1',INDEX)((A(I),I=I1,I1+I2),I1=1,I3,NCOLS)
NRW=NRW+1
RETURN

```

```

C
ENTRY RSTR(A,IA,INDEX)
IF(INDEX.LT.1.OR.INDEX.GT.KOUNT) GO TO 801
READ(IFILE2',INDEX)IB
IF(IB(3).EQ.0) CALL QUIT(INDEX)
C
CHECK TO SEE IF THE DIMENSIONS OF THE MATRIX ARE LARGE ENOUGH
IF(IB(1).GT.1A(3)) CALL QUIT(1)
IF(IB(2).GT.1A(4)) CALL QUIT(1)
IA(1)=IB(1)
IA(2)=IB(2)
NR=IA(1)
NC=IA(2)
NCOLS=IA(4)
I2=NR-1
I3=NCOLS*(NR-1)+1
READ(IFILE1',INDEX)((A(I),I=I1,I1+I2),I1=1,I3,NCOLS)
NRW=NRW+1
RETURN

```

```

C
ENTRY FINISH
CALL NEWPAG
CALL NEWLIN
WRITE(IOFILE,1111)NRW
1111 FORMAT(110,21H READ-WRITES EXECUTED)
CALL NEWLIN
WRITE(IOFILE,6)
6 FORMAT(12H NORMAL HALT)
STOP

```

```

C
ENTRY SETSIZ(NUMBR)
MAXWRD=NUMBR
CALL RANSIZ(IFILE1,MAXWRD,0)
CALL RANSIZ(IFILE2,3)
RETURN

```

C

```

ENTRY SETNUM(NUMBR)
MAXKNT=NUMBR
CALL SETDUM(NUMBR)
RETURN

```

C

```

ENTRY NEWNUM(NUMBR)
KOUNT=KOUNT+1
IF(KOUNT.LE.MAXKNT) GO TO 501
WRITE(IOFILE,502)MAXKNT
502 FORMAT(10H MORE THAN,110, 9H MATRICES)
CALL QUIT(1)
501 CONTINUE
NUMBR=KOUNT
IB(1)=0
IB(2)=0
IB(3)=0
WRITE(IOFILE2,KOUNT)IB
RETURN

```

C

```

ENTRY MATZER(A,IA)
NSQ=IA(3)*IA(4)
DO 1 I=1,NSQ
1 A(I)=0.0
RETURN

```

C

C

```

TO NEGATE A MATRIX
ENTRY MNEG(A,IA)
NSQ=IA(3)*IA(4)
DO 82 I=1,NSQ
82 A(I)=-A(I)
RETURN

```

C

```

ENTRY MATIDN(A,IA,NUM)
IF(IA(3).LT.NUM.OR.IA(4).LT,NUM) CALL QUIT(1)
IA(1)=NUM
IA(2)=NUM
NSQ=IA(3)*IA(4)
DO 2 I=1,NSQ
2 A(I)=0.0
DO 3 I=1,NUM
NSQ=IA(3)*((I-1) + I
3 A(NSQ)=1.0

```

```

      RETURN
C
801 CALL NEWLIN
      WRITE(IOFILE,802)INDEX
802 FORMAT(20H BAD MATRIX INDEX OF,110)
      CALL QUIT(1)
      STOP
C
      END SAVE
      END
CNEWLIN      NEWLIN
      SUBROUTINE NEWLIN
      COMMON /DATTIM/ITIME(2),IDATE(2)
      PARAMETER MAX=20
      DIMENSION IHEAD(MAX)
      DIMENSION JHEAD(MAX)
      DIMENSION IVEC(NWORDS)
      DATA JHEAD/MAX*6H /
      DATA IOFILE/6/
      DATA MAXLIN/55/
      DATA INAME/1H /
      DATA NLINES/0/
      DATA I001/1/
      DATA IPAGE/0/
      DATA N2/3/
      DATA IBLANK/1H /
      I002=1
      GO TO ( 1,32),I001
32 IF(NLINES.GT.0) GO TO 5
      IPAGE=IPAGE+1
      WRITE(IOFILE,10)
10 FORMAT(1H1,/)
      WRITE(IOFILE,6) ITIME,      IDATE,IPAGE
6 FORMAT( 9H TIME IS ,2A6 , 4H ON ,      2A6,80X,
1 5HPAGE=,15)
      WRITE(IOFILE,87)JHEAD
87 FORMAT(10H      TITLE=,20A6)
      WRITE(IOFILE,7) IHEAD
7 FORMAT(10H SUBTITLE=,20A6)
      DO 8 J=1,N2
8 WRITE(IOFILE,9)
9 FORMAT(1H )
      NLINES=N2+3
5 NLINES=NLINES+1

```

```
IF(NLINES.GT,MAXLIN)NLINES=0  
RETURN
```

C

```
ENTRY NEWPAG  
NLINES=0  
RETURN
```

C

```
ENTRY SETHED(NWORDS,IVEC)  
IG02=2  
GO TO (1,2),IG01  
1 CALL TIMDAT( ITIME,IDATE)  
IG01=2  
2 NLINES=0  
IPAGE=0  
DO 3 I=1,MAX  
3 IHEAD(I)=IBLANK  
GO TO (32,22),IG02  
22 DO 4 I=1,NWORDS  
4 IHEAD(I)=IVEC(I)  
RETURN
```

C

```
ENTRY SUPERT(NWORDS,IVEC)  
DO 80 I=1,NWORDS  
80 JHEAD(I)=IVEC(I)
```

```
RETURN
```

C

```
END NEWLIN  
END
```

CQUIT

QUIT

```
SUBROUTINE QUIT(IERR)  
COMMON /FILES/INFILE,IOFILE,IFILE1,IFILE2  
DIMENSION IB(3)  
NSQ=0  
NSQ=NSQ**NSQ  
WRITE(IOFILE,21)IERR  
21 FORMAT(22H QUIT BECAUSE OF IERR=,I10)  
IG0=1  
GO TO 777
```

C

```
ENTRY MATHAT  
IG0=0  
777 CONTINUE  
WRITE(IOFILE,12)  
12 FORMAT(19H MATRIX INFORMATION)
```

	WRITE(IOFILE,13)	MATRIX NUMBER EVER USED)	NO. ROWS IN USE	NO. COLS IN
13	FORMAT(80H			
1	USE			
	DO 10 I=1,MAXKNT			
	READ(IFILE2'1)IB			
10	WRITE(IOFILE,11)1,IB			
11	FORMAT(4I20)			
	IF(IGO,EQ,0) RETURN			
	CALL PDUMP			
	STOP			
C	ENTRY SETDUM(IERR)			
	MAXKNT=IERR			
	RETURN			
C	END QUIT			
	END			
*INVR5	SUBROUTINE TO OBTAIN INVERSE OF MATRIX, CALL DECOM FIRST			INVR5020
*	CD600D4.007 DATE 05/04/65			INVR5030
	SUBROUTINE INVR5(A,INTR,MSIZE,NN)			INVR5040
	DIMENSION A(MSIZE,MSIZE),INTR(MSIZE)			INVR5050
*	OBTAINS EXPLICIT INVERSE OF DECOMPOSED MATRIX			INVR5060
*	SUBROUTINE DECOM MUST BE CALLED FIRST			INVR5070
	N=NN			INVR5080
	IF(INTR(N))18,17,18			INVR5090
1	DO 13 K=1,N			INVR5100
	KM=K-1			INVR5110
	IF(KM)2,7,2			INVR5120
2	IF(K-N)3,7,3			INVR5130
*	COMPLETE REDUCTION BELOW DIAGONAL			INVR5140
3	KP=K+1			INVR5150
	DO 6 I=KP,N			INVR5160
	X=A(I,K)			INVR5170
	IF(X)4,6,4			INVR5180
4	DO 5 J=1,KM			INVR5190
5	A(I,J)=A(K,J)+X*A(I,J)			INVR5200
6	CONTINUE			INVR5210
*	DIVIDE THROUGH BY PIVOT ELEMENT			INVR5220
7	X=1.0/A(K,K)			INVR5230
	A(K,K)=1.0			INVR5240
	DO 8 J=1,N			INVR5250
8	A(K,J)=A(K,J)+X			INVR5260
	IF(KM)9,13,9			INVR5270
*	REDUCE TERMS ABOVE DIAGONAL			INVR5280



9	DO 12 I=1,KM	INVRS290
	X=-A(I,K)	INVRS300
	IF(X)10,12,10	INVRS310
10	A(I,K)=0.0	INVRS320
	DO 11 J=1,N	INVRS330
11	A(I,J)=A(K,J)*X+A(I,J)	INVRS340
12	CONTINUE	INVRS350
13	CONTINUE	INVRS360
*	INTERCHANGE COLUMNS	INVRS370
*	KM=N-1 FROM PREVIOUS LOOP	INVRS380
	DO 16 J=1,KM	INVRS390
	K=N-J	INVRS400
	KP=INTR(K)	INVRS410
	IF(KP)14,16,14	INVRS420
14	DO 15 I=1,N	INVRS430
	X=A(I,KP)	INVRS440
	A(I,KP)=A(I,K)	INVRS450
15	A(I,K)=X	INVRS460
16	CONTINUE	INVRS470
17	RETURN	INVRS480
18	KM=N-1	INVRS490
	DO 21 I=2,KM	INVRS500
	K=INTR(I)	INVRS510
	IF(K)19,21,19	INVRS520
19	KP=I-1	INVRS530
	DO 20 J=1,KP	INVRS540
	X=A(I,J)	INVRS550
	A(I,J)=A(K,J)	INVRS560
20	A(K,J)=X	INVRS570
21	CONTINUE	INVRS580
	GO TO 1	INVRS590
	END	INVRS600
*MINV	MATRIX INVERSE ROUTINE	MINV0020
*	CD600D4.007      DATE 05/04/65	MINV0030
	SUBROUTINE MINV(A,MSIZE,N,INTR,DET)	MINV0040
	DIMENSION A(MSIZE,MSIZE),INTR(MSIZE)	MINV0050
	CALL DECOM(A,INTR,MSIZE,N)	MINV0060
	CALL DTMN(A,INTR,MSIZE,N,DET)	MINV0070
	CALL INVRS(A,INTR,MSIZE,N)	MINV0080
	RETURN	MINV0130
	END	MINV0140
*MMPY	CD600D4.012      MATRIX MULTIPLY ROUTINE 05/18/66	MMPY0002
*	COPYRIGHT 1966 BY GENERAL ELECTRIC COMPANY	MMPY0003

SUBROUTINE MHPY(A,IDA,B,IDB,C,IDC,IND)	MHPY0040
DIMENSION A(1),B(1),C(1),IDA(4),IDB(4),IDC(4)	MHPY0050
IA=IDA(1)	MHPY0060
JA=IDA(2)	MHPY0070
MA=IDA(3)	MHPY0080
IB=IDB(1)	MHPY0090
JB=IDB(2)	MHPY0100
MB=IDB(3)	MHPY0110
IC=IDC(1)	MHPY0120
JC=IDC(2)	MHPY0130
MC=IDC(3)	MHPY0140
NC=IDC(4)	MHPY0150
IND=0	MHPY0160
IF(JA.NE.IB)IND=2	
IF((MC.LT.IA).OR.(NC.LT.JB))IND=1	MHPY0180
IF(IND.NE.0)RETURN	MHPY0190
IDC(1)=IDA(1)	
IDC(2)=IDB(2)	
DO 1 I=1,IA	MHPY0200
DO 1 K=1,JB	
LC=MC+(K-1)+I	MHPY0220
C(LC)=0.0	MHPY0230
KB=MB+(K-1)	MHPY0240
DO 1 J=1,IB	
LA=MA+(J-1)+I	MHPY0260
LB=KB+J	MHPY0270
1 C(LC)=C(LC)+A(LA)*B(LB)	MHPY0280
RETURN	MHPY0290
END	MHPY0300
*MADD	MADD0002
CD60004.010 MATRIX ADD ROUTINE 05/18/66	MADD0003
COPYRIGHT 1966 BY GENERAL ELECTRIC COMPANY	MADD0040
SUBROUTINE MADD(A,IDA,B,IDB,C,IDC,IND)	MADD0050
DIMENSION A(1),B(1),C(1),IDA(4),IDB(4),IDC(4)	MADD0060
IA=IDA(1)	MADD0070
JA=IDA(2)	MADD0080
IB=IDB(1)	MADD0090
JB=IDB(2)	MADD0093
IC=IDC(1)	MADD0096
JC=IDC(2)	MADD0100
MA=IDA(3)	MADD0110
MB=IDB(3)	MADD0120
MC=IDC(3)	MADD0130
NC=IDC(4)	

IND=0	MADD0140
IF((IA.NE.IB).OR.(JA.NE.JB))IND=2	
IF((MC.LT.IA).OR.(NC.LT.JA))IND=1	MADD0160
IF(IND.NE.0)RETURN	MADD0170
IDC(1)=IDA(1)	
IDC(2)=IDA(2)	
DO 1 J=1,JA	MADD0180
JM=J-1	MADD0190
LA=MA+JM	MADD0200
LB=MB+JM	MADD0210
LC=MC+JM	MADD0220
DO 1 I=1,IA	MADD0230
LA=LA+1	MADD0240
LB=LB+1	MADD0250
LC=LC+1	MADD0260
1 C(LC)=A(LA)+B(LB)	MADD0270
RETURN	MADD0280
END	MADD0290
*MSUB	CD60004.011 MATRIX SUBTRACT ROUTINE 05/18/66
*	COPYRIGHT 1966 BY GENERAL ELECTRIC COMPANY
SUBROUTINE MSUB(A,IDA,B,IDB,C,IDC,IND)	MSUB0002
DIMENSION A(1),B(1),C(1),IDA(4),IDB(4),IDC(4)	MSUB0003
IA=IDA(1)	MSUB0004
JA=IDA(2)	MSUB0005
IB=IDB(1)	MSUB0006
JB=IDB(2)	MSUB0007
IC=IDC(1)	MSUB0008
JC=IDC(2)	MSUB0009
MA=IDA(3)	MSUB0010
MB=IDB(3)	MSUB0011
MC=IDC(3)	MSUB0012
NC=IDC(4)	MSUB0013
IND=0	MSUB0014
IF((IA.NE.IB).OR.(JA.NE.JB))IND=2	
IF((MC.LT.IA).OR.(NC.LT.JA))IND=1	MSUB0160
IF(IND.NE.0)RETURN	MSUB0170
IDC(1)=IDA(1)	
IDC(2)=IDA(2)	
DO 1 J=1,JA	MSUB0180
JM=J-1	MSUB0190
LA=MA+JM	MSUB0200
LB=MB+JM	MSUB0210
LC=MC+JM	MSUB0220

DO 1 I=1,IA	MSUB0230
LA=LA+1	MSUB0240
LB=LB+1	MSUB0250
LC=LC+1	MSUB0260
1 C(LC)=A(LA)-B(LB)	MSUB0270
RETURN	MSUB0280
END	MSUB0290
*DECOM SUBROUTINE TO DECOMPOSE MATRIX FOR SIMULTANEOUS EQUATIONS	DECOM020
CD600D4,007 DATE 05/04/65	DECOM030
SUBROUTINE DECOM(A,INTR,MSIZE,NH)	DECOM040
DIMENSION A(MSIZE,MSIZE),INTR(MSIZE)	DECOM050
* MATRIX DECOMPOSITION USED WITH SOLV SUBROUTINE FOR SOLUTION	DECOM060
* OF LINEAR SYSTEMS	DECOM070
* IF MATRIX A IS SINGULAR INTR(N) WILL BE SET TO ZERO	DECOM080
N=NH	DECOM090
NTR=1	DECOM100
NH=N-1	DECOM110
DO 10 J=1,NH	DECOM120
AMAX=ABS(A(J,J))	DECOM130
JP=J+1	DECOM140
IN=0	DECOM150
DO 2 I=JP,N	DECOM160
AT=ABS(A(I,J))	DECOM170
IF (AMAX-AT)1,2,2	DECOM180
1 AMAX=AT	DECOM190
IN=I	DECOM200
2 CONTINUE	DECOM210
IF (AMAX)4,3,4	DECOM220
3 INTR(J)=J	DECOM230
GO TO 11	DECOM240
4 IF (IN)5,7,5	DECOM250
5 NTR=-NTR	DECOM260
DO 6 I=J,N	DECOM270
AT=A(J,I)	DECOM280
A(J,I)=A(IN,I)	DECOM290
6 A(IN,I)=AT	DECOM300
7 INTR(J)=IN	DECOM310
AMAX=-1.0/A(J,J)	DECOM320
DO 10 I=JP,N	DECOM330
IF (A(I,J))8,10,8	DECOM340
8 AT=A(I,J)*AMAX	DECOM350
A(I,J)=AT	DECOM360
DO 9 K=JP,N	DECOM370

9	A(I,K)=A(J,K)*AT+A(I,K)	DECOM380
10	CONTINUE	DECOM390
	IF(A(N,N))12,11,12	DECOM400
11	NTR=0	DECOM410
12	INTR(N)=NTR	DECOM420
	RETURN	DECOM430
	END	DECOM440
*DTMN	DETERMINANT EVALUATION SUBROUTINE	DTMN0020
	CD6000D4.007 DATE 05/04/65	DTMN0030
	SUBROUTINE DTMN(A,INTR,MSIZE,NN,DET)	DTMN0040
	DIMENSION A(MSIZE,MSIZE),INTR(MSIZE)	DTMN0050
	COMPUTES DET, THE DETERMINANT OF THE DECOMPOSED MATRIX	DTMN0060
	SUBROUTINE DECOM MUST BE CALLED FIRST	DTMN0070
	INTR(N) WILL CONTAIN INTEGER POWER OF TEN OF MULTIPLYING FACTOR	DTMN0080
	EP=1.E38	DTMN0090
	NE=38	DTMN0100
	A=NN	DTMN0110
	INTR=INTR(N)	DTMN0120
	IF(INTR)2,1,3	DTMN0130
1	DTT=0.0	DTMN0140
	GO TO 10	DTMN0150
2	DTT=-10.	DTMN0160
	GO TO 4	DTMN0170
3	DTT=0.1	DTMN0180
4	DO 9 I=1,N	DTMN0190
	DT=ABS(DTT)	DTMN0200
	IF(ABS(A(I,1))-1.0)5,9,7	DTMN0210
5	IF(DT-1.)6,9,9	DTMN0220
6	DTT=DTT*EP	DTMN0230
	NTR=NTR-NE	DTMN0240
	GO TO 9	DTMN0250
7	IF(DT-1.0)9,9,8	DTMN0260
8	DTT=DTT/EP	DTMN0270
	NTR=NTR+NE	DTMN0280
9	DTT=DTT*A(I,1)	DTMN0290
	INTR(N)=NTR	DTMN0300
10	DET=DTT	DTMN0310
	RETURN	DTMN0320
	END	DTMN0330
*PMAT	SUBROUTINE TO PRINT MATRIX	PMAT0020
	SUBROUTINE PMAT(A,NR,NC,MM,NN)	PMAT0050
	DIMENSION A(MM,NN),P(6)	PMAT0060
	NROW=NR	

NCOL=NC

I=1

J=1

PMAT0070

PMAT0080

PMAT0090

1 IP=1

JP=J

PMAT0100

DO 2 K=1,6

PMAT0110

KK=K

PMAT0120

P(K)=A(I,J)

PMAT0130

J=J+1

PMAT0140

IF(J.GT.NCOL)GO TO 3

PMAT0150

2 CONTINUE

PMAT0160

CALL NEWLIN

PMAT0170

WRITE(6,4)IP,JP,(P(K),K=1,KK)

4 FORMAT(2I4,6(1PE16,8))

PMAT0180

GO TO 1

PMAT0190

3 CALL NEWLIN

PMAT0200

WRITE(6,4)IP,JP,(P(K),K=1,KK)

I=I+1

J=1

PMAT0220

IF(I.LE.NROW)GO TO 1

PMAT0230

RETURN

PMAT0240

END

PMAT0250

\$

OMAP

DECK

PMAT0260

\$

INCODE

IBMF

GETMOR

LBL

GETMOR,GETMOR

TTL

GETMOR

SYNDEF

GETMOR

REM

TO OBTAIN MORE CORE OR DISC

REM

CALL GETMOR(TYPE,RESULT,NUM,FC)

REM

TYPE=0 FOR CORE

REM

TYPE=1 FOR RANDOM DISC

REM

TYPE=2 FOR LINKED DISC

REM

RESULT=0 IF SUCCESSFUL

REM

RESULT=1 IF UNSUCCESSFUL

REM

NUM IS NUMBER OF LINKS DESIRED OR

REM

NUMBER OF K (1024 WORDS) DESIRED

REM

FC IS THE FILE CODE IN THE FORM 6H0000FC

REM

(USED ONLY WHEN GETTING MORE DISC)

GETMOR

LDA

4,1\*

LDB

2,1\*

SBC

=6H0000001

TMI

STORA

CORE REQUEST

TZE

RANDOM

RANDOM DISC REQUEST

			LINKED DISC REQUEST	
	LDD	5,1*		
	TRA	ORTOA		
RANDOM	LDD	5,1*		
	ORD	=1,DU		
ORTOA	ORA	=2,DU		
STORA	STA	ZERO		
	MME	GEMORE		
ZERO	BSS	1		
	TRA	NO		
YES	LDD	=6H000000		
	TRA	CONT		
NO	LDD	=6H000001		
CONT	STQ	3,1*		
	TRA	0,1		
	END			
S	GMAP	DECK,COMDK	81524	090672GIMME
S	INCODE	IBMF		
	TTL	GIVE-ME-MORE-CORE		IMME0001
	LBL	GIMME,GIVE-ME-MORE-CORE		IMME0002
*				IMME0003
*	SUBROUTINE TO ADJUST SIZE OF SPECIFIED ARRAY TO SPECIFIED			IMME0004
*	NEW SIZE. MME GEMORE IS USED TO ADD MORE WORDS OF MEMORY.			IMME0005
*	MME GEMREL IS USED TO RELEASE SURPLUS WORDS OF MEMORY.			IMME0006
*				IMME0007
*	CALLING SEQUENCE			IMME0008
*	CALL GIMME ( NEWSIZ, OLDSIZ, ARRAY NAME )			IMME0009
*				IMME0010
*	THE ARRAY SPECIFIED MUST BE LOADED AT THE VERY TOP OF MEMORY,			IMME0011
*	USING EITHER A S USE CONTROL CARD OR A BLOCK DATA SUBPROGRAM,			IMME0012
*	( IT IS ALSO NECESSARY THAT THE ARRAY BE IN LABELED COMMON. )			IMME0013
*				IMME0014
*	WARNING--THIS SUBROUTINE CHANGES THE SECOND ARGUMENT			IMME0015
*	TO REFLECT THE NEW SIZE OF THE ARRAY			IMME0016
*				IMME0017
	SYNREF	.FCNV.		
GIMME	SAVE			IMME0018
*				IMME0019
*	THESE NEXT INSTRUCTIONS ARE USED TO MONITOR PERFORMANCE OF GIMME			IMME0020
*	THEY MAY BE REMOVED IF NOT WANTED, ALONG WITH THE CODE AT SYMBOL			IMME0021
*	DONE. SET DONE EQU GIMME+1 IF REMOVED.			IMME0022
*				IMME0023
	MME	GETIME	GET TIME OF DAY	IMME0024
	STQ	TEMP2+1		IMME0025

	MME STD	GELAPS TEMP2	GET PROCESSOR TIME USED TILL NOW	IMME0026
				IMME0027
				IMME0028
*	CHECK THAT THE REFERENCED ARRAY IS LOADED AT THE TOP OF CORE			IMME0029
*				IMME0030
	SBAR	**1	GET THE ADDRESS OF THE TOP OF CORE	IMME0031
	LDQ	**DL		IMME0032
	AND	=0777,DL		IMME0033
	QLS	9		
	EAX0	4,1*	GET ADDRESS OF ARRAY	
	STX0	ARADR	SAVE	
ARADR	SBQ	**DL	SUBTRACT ADDRESS OF ARRAY	
	LDA	LOWLOD	CHECK LOWLOAD	
	CANA	=1B18,DL	INDICATOR	
	TNZ	LOW	...LOWLOADED	
*				
*	HIGHLOAD PRE-PROCESS AND CHECKS			
*				
	LDA	=1,DU	SET FLAG	
	STCA	RLSFLQ,70	TO ALLOW MEMORY RELEASE	
	STQ	TEMP	SAVE ARRAY SIZE	
	SBQ	3,1*	SUBTRACT CLAIMED ARRAY SIZE	
	TZE	**3	...EQUAL	
	CMPQ	1,DU	MAYBE ARRAY WAS LOADED ON ODD LOCATION	IMME0039
	TNZ	ERROR	... SORRY, SOMETHING ELSE AT TOP OF CORE	IMME0040
	LDQ	TEMP	RESTORE ARRAY SIZE	
	TRA	GIM	...CONTINUE	
*				
*	LOWLOAD PREPROCESS AND CHECKS			
*				
LOW	LDX0	ARADR	ADDRESS OF ARRAY	
	CMPX0	LIMITS	COMPARE WITH LOWEST UNUSED	
	TMI	ERROR	...ARRAY NOT LOADED ABOVE PROGRAM	
	LXL0	LIMITS	ADDRESS OF HIGH UNUSED LIMIT	
	CMPX0	ARADR	COMPARE WITH BASE OF ARRAY	
	TMI	**4	...OK, LIMIT IS BELOW BASE	
	LDX0	ARADR	ADJUST LIMIT	
	SBLX0	=1,DU	TO BE	
	SXL0	LIMITS	BELOW ARRAY	
	LDA	2,1*	COMPUTE FLAG	
	SBA	3,1*	INDICATING THAT	
	STCA	RLSFLQ,70	RELEASE MAY OCCUR (IF NEGATIVE)	
GIM	STC	3,1*	MAKE SURE OLD ARRAY SIZE IS CORRECT	



* COMPUTE THE NUMBER OF 1024 WORD BLOCKS THAT ARE REQUIRED			IMME0041
			IMME0042
			IMME0043
LDC	2,1*	NUMBER OF WORDS REQUIRED	IMME0044
SBO	3,1*	NUMBER OF WORDS ALREADY IN THE ARRAY	IMME0045
ADQ	=1023,DL	ROUNDING UP FACTOR	IMME0049
ORS	10	DIVIDE BY 1024	IMME0050
STQ	TEMP	SAVE NUMBER OF K TO GROW	
TZE	DONE	...NO CORE ADJUSTMENT REQUIRED	
* IF GIMME IS NOT TO RELEASE CORE, INSERT THE FOLLOWING INSTRUCTION			
* HERE			
****	TMI	DONE	...NO MORE CORE REQUIRED
	LDA	TEMP	UPDATE THE NUMBER
	ALS	10	OF WORDS IN
	ASA	3,1*	THE ARRAY
* IF GIMME IS NOT TO RELEASE SURPLUS CORE, REMOVE THE FOLLOWING TWO			IMME0056
* INSTRUCTIONS.			IMME0057
	CMPA	0,DL	IMME0058
	TMI	GIVEUP	... CORE CAN BE RELEASED
			IMME0059
* LOOP TO FETCH REQUIRED CORE IN 2K INCREMENTS			IMME0060
			IMME0061
LOOP	STQ	TEMP3	SAVE THE NUMBER OF K
	CMPQ	1,DL	HOW MANY MORE K
	TZE	LAST	... GET 1K MORE
	MME	GEMORE	GET 2K MORE
	ZERO	0,2	
	TSX1	CNT	... CORE REQUEST REFUSED
	LDD	TEMP3	UPDATE THE
	SBO	2,DL	NUMBER OF K
	TZE	DONE	... DONE
	TRA	LOOP	... CONTINUE
LAST	MME	GEMORE	GET THE LAST 1K BLOCK
	ZERO	0,1	
	TSX1	CNT	... CORE REQUEST REFUSED
	TRA	DONE	... DONE
			IMME0077
CNT	AOS	COUNT	COUNT NUMBER OF REQUESTS REFUSED
	LDD	4*1000+64,DL	GO TO SLEEP FOR A WHILE
	MME	GEWAKE	... ZZZ Z Z Z Z Z Z
	TRA	-3,1	... TRY AGAIN
			IMME0081
			IMME0082
* SEQUENCE TO RELEASE SURPLUS CORE			IMME0083

GIVEUP	SZN	** ,DU	CHECK RELEASE FLAG	IMME0084
	TPL	DONE	... POSITIVE, NO RELEASE REQUESTED	
	LCQ	TEMP	GET ABSOLUTE VALUE OF NUMBER OF BLOCKS	
	QLS	10	MULTIPLY BY 1024	IMME0086
	EAA	DONE	SET RETURN ADDRESS FOR GEMREL	IMME0087
	MME	GEMREL	... RELEASE CORE	IMME0088
				IMME0089
				IMME0090
				IMME0091
DONE	MME	GELAPS	COMPUTE PROCESSOR TIME USED BY GIMME	IMME0092
	SSQ	TEMP2		IMME0093
	MME	GETIME	COMPUTE ELAPSED TIME	IMME0094
	SRQ	TEMP2+1		IMME0095
	TPL	**2	... DID NOT PASS MIDNIGHT	
	ADQ	=5.5296E9	ADD 24 HOURS TO CORRECT	
	TOV	**1	CONVERT TO FLOATING POINT	IMME0096
	LDA	0,DL		IMME0097
	LDE	=71825,DU		IMME0098
	FNO			IMME0099
	FDV	=2.304E8	CONVERT TO HOURS FROM 64THS OF MILLISEC.	IMME0100
	FST	TEMP2+1	SAVE FOR PRINTING	IMME0101
	LQD	TEMP2	CONVERT PROC. TIME TO HOURS	
	TOV	**1		
	LDA	0,DL		
	LDE	=71825,DU		
	FNO			
	FDV	=2.304E8		
	FST	TEMP2		
	CALL	.FPRN,(FILE,FORM1)		
	LDA	TEMP	PRINT NUMBER K CORE	
	TSX1	.FCNV.		
	LDA	COUNT	PRINT NUMBER OF REQUESTS REFUSED	IMME0103
	TSX1	.FCNV.		IMME0105
	LDA	TEMP2	PRINT PROCESSOR TIME USED BY GIMME	IMME0106
	TSX1	.FCNV.		IMME0107
	LDA	TEMP2+1	PRINT ELAPSED TIME	IMME0108
	TSX1	.FCNV.		IMME0109
	CALL	.FFIL.		IMME0110
	STZ	COUNT	RESET FOR NEXT CALL TO GIMME	IMME0111
	RETURN	GIMME		IMME0112
				IMME0113
ERROR	CALL	FXEM(=61,MESS,=5)		

RLSFL6	EQU	GIVEUP		
LIMITS	BOOL	37		
LOWLOD	BOOL	24		
TEMP	BSS	1		IMME0115
TEMP2	BSS	2	STORAGE FOR PROCESSOR AND ELAPSED TIME	IMME0116
TEMP3	BSS	1		
COUNT	ZERO			IMME0117
MESS	BCI	5, ARRAY NOT LOADED ABOVE PROGRAM		
FORM1	BCI	9, (19H GIMME1 REQUEST FOR 14.10HK REFUSED 15.13H TIMES,		
	BCI	8, USED 17.6, 11H HR, PROC., 17.4, 11H HR, ELAPS.)		
	BLOCK	GIMMEB		
FILE	DEC	06		
	END			IMME0121
S	QMAP	DECK, COMDK	77739	G11671 TIME
S	INCODE	IRMF		
	LBL	TIME, TIME AND DATE SUBPROGRAM		TIME0010
	TTL	DRILL CONVERSION PROGRAM		TIME0020
	TTL5	TIME, DATE, AND ELAPSED TIME SUBPROGRAM		TIME0030
*				TIME0040
*	CALL	TIMDAT (TIME, DATE)		TIME0050
*				TIME0060
*	WHERE	TIME = 2 CONSECUTIVE WORDS WHERE THE CURRENT TIME WILL BE		TIME0070
*		PLACED AS HH:MM:SS		TIME0080
*	DATE	= 2 CONSECUTIVE WORDS WHERE THE CURRENT DATE WILL BE		TIME0090
*		PLACED AS MM/DD/YY		TIME0100
*				TIME0110
*	TIMDAT	SAVE 0		TIME0120
	NME	GETIME	GET DATE IN A AS MMDDYY AND TIME IN Q IN	TIME0130
	REM		64 THS MSEC SINCE MIDNIGHT.	TIME0140
	STQ	TIME	SAVE TIME	TIME0150
	LRL	36	PLACE DATE IN Q	TIME0160
	LDA	=6H	PLACE SPACES IN A	TIME0170
	LLR	12	MOVE MM INTO A	TIME0180
	ALS	6		TIME0190
	ORA	=3H00/, DL	INSERT SLASH	TIME0200
	LLR	12	MOVE DD INTO A	TIME0210
	ALS	6		TIME0220
	ORA	=3H00/, DL	INSERT SLASH	TIME0230
	LDXQ	3, 1	LOAD ADDRESS OF DATE	TIME0240
	STA	0, 0	STORE FIRST	TIME0250
	STQ	1, 0	AND SECOND WORD	TIME0260
	LDO	TIME	PUT TIME IN Q	TIME0270
	ORS	6	CONVERT TO MSEC	TIME0280

DIV	1000,DL	CONVERT TO SEC	TIME0290
DIV	10,DL		TIME0300
STA	TIME	STORE UNIT SECONDS	TIME0310
DIV	6,DL		TIME0320
STA	TIME+1	STORE TEN'S OF SECONDS	TIME0330
DIV	10,DL		TIME0340
STA	TIME+2	STORE UNIT MINUTES	TIME0350
DIV	6,DL		TIME0360
STA	TIME+3	STORE TEN'S OF MINUTES	TIME0370
DIV	10,DL	UNIT HRS TO A, 10'S OF HRS IN Q	TIME0380
ALS	30		TIME0390
LLR	6	ASSEMBLE MH IN RIGHT OF Q	TIME0400
QLS	6		TIME0410
ORQ	=015,DL	INSERT COLON	TIME0420
QLS	6		TIME0430
ORQ	TIME+3		TIME0440
QLS	6		TIME0450
ORQ	TIME+2	INSERT MH	TIME0460
QLS	6		TIME0470
ORQ	=015,DL	INSERT COLON	TIME0480
LDA	=6H	PLACE SPACES IN A	TIME0490
LLS	6		TIME0500
ORQ	TIME+1		TIME0510
LLS	6		TIME0520
ORQ	TIME	INSERT SS	TIME0530
LLR	24		TIME0540
LDO	2,1	LOAD ADDRESS OF TIME	TIME0550
STA	0,0	STORE FIRST AND	TIME0560
STQ	1,0	SECOND WORD	TIME0570
RETURN	TIMEAT		TIME0580
EJECT			TIME0590
*			TIME0600
*	CALL ELTIME(TIMEI)		TIME0610
*			TIME0620
*	WHERE TIMEI = LOCATION WHERE ELAPSED TIME IN MSEC. IS PLACED.		TIME0630
*			TIME0640
ELTIME	SAVE		TIME0650
MME	GELAPS	GET ELAPSED TIME IN Q IN 64'THS MSEC.	TIME0660
QRS	6	CONVERT TO MSEC	TIME0670
STQ	2,1*	STORE IN TIMEI	TIME0680
RETURN	ELTIME		TIME0690
TIME	BSS		TIME0700
END			TIME0710

```

$ EXECUTE
$ FFILE 07
$ FILE 08,,1R
$ LIMITS 200,17K,,20K
TITLE THERMAL TEST CASE
SIZE 50
HEAT 1 5
$ ENDJOB

```